



复旦微电子

***FM25S01A***  
***3.3V 1G-BIT SPI NAND FLASH***  
***MEMORY***

**Datasheet**

---

**Aug. 2018**

INFORMATION IN THIS DOCUMENT IS INTENDED AS A REFERENCE TO ASSIST OUR CUSTOMERS IN THE SELECTION OF SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD PRODUCT BEST SUITED TO THE CUSTOMER'S APPLICATION; THEY DO NOT CONVEY ANY LICENSE UNDER ANY INTELLECTUAL PROPERTY RIGHTS, OR ANY OTHER RIGHTS, BELONGING TO SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD OR A THIRD PARTY.

WHEN USING THE INFORMATION CONTAINED IN THIS DOCUMENTS, PLEASE BE SURE TO EVALUATE ALL INFORMATION AS A TOTAL SYSTEM BEFORE MAKING A FINAL DECISION ON THE APPLICABILITY OF THE INFORMATION AND PRODUCTS. PURCHASERS ARE SOLELY RESPONSIBLE FOR THE CHOICE, SELECTION AND USE OF THE SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD PRODUCTS AND SERVICES DESCRIBED HEREIN, AND SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD ASSUMES NO LIABILITY WHATSOEVER RELATING TO THE CHOICE, SELECTION OR USE OF THE SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD PRODUCTS AND SERVICES DESCRIBED HEREIN. UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD REPRESENTATIVE, SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE.

FUTURE ROUTINE REVISIONS WILL OCCUR WHEN APPROPRIATE, WITHOUT NOTICE. CONTACT SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD SALES OFFICE TO OBTAIN THE LATEST SPECIFICATIONS AND BEFORE PLACING YOUR PRODUCT ORDER. PLEASE ALSO PAY ATTENTION TO INFORMATION PUBLISHED BY SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD BY VARIOUS MEANS, INCLUDING SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD HOME PAGE ([HTTP://WWW.FMSH.COM](http://www.fms.com)).

PLEASE CONTACT SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD LOCAL SALES OFFICE FOR THE SPECIFICATION REGARDING THE INFORMATION IN THIS DOCUMENT OR SHANGHAI FUDAN MICROELECTRONICS GROUP CO., LTD PRODUCTS.

## Trademarks

Shanghai Fudan Microelectronics Group Co., Ltd name and logo, the “复旦” logo are trademarks or registered trademarks of Shanghai Fudan Microelectronics Group Co., Ltd or its subsidiaries in China.

Shanghai Fudan Microelectronics Group Co., Ltd, Printed in the China, All Rights Reserved.

# 1. Description

The FM25S01A is a 1G-bit (128M-byte) SPI (Serial Peripheral Interface) NAND Flash memory, with advanced write protection mechanisms. The FM25S01A supports the standard Serial Peripheral Interface (SPI), Dual/Quad I/O option.

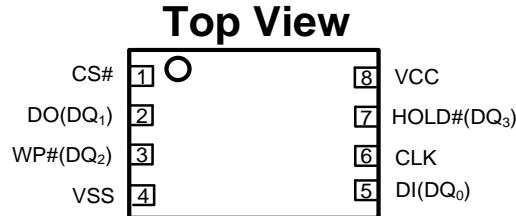
# 2. Features

- **1G-bit NAND Flash Memory**
  - Single-level cell (SLC) technology
  - Page size : 2112bytes(2048 + 64bytes)
  - Block size : 64 pages(128K + 4K bytes)
  - Device size: 1Gb(1024 blocks)
- **Serial Interface**
  - Standard SPI: CLK, CS#, DI, DO, WP#
  - Dual SPI: CLK, CS#, DQ0, DQ1, WP#
  - Quad SPI: CLK, CS#, DQ0, DQ1, DQ2, DQ3
- **High Performance**
  - 104MHz for fast read
  - Quad I/O data transfer up to 416Mbits/s
- **Supply Voltage**
  - FM25S01A:2.7V~3.6V
- **Low Power, Wide Temperature Range**
  - 20mA active current
  - -40~85°C operating range
- **Program/Erase/Read Speed**
  - PAGE PRPGRAM time : 400μs typical
  - BLOCK ERASE time : 4ms typical
  - PAGE READ time :
    - 100μs maximum (with ECC)
    - 25μs maximum (without ECC)
- **Advanced Features for NAND**
  - 1bit Internal ECC option, per 512 bytes
  - Software and Hardware Write-Protect
  - 32B Unique ID and 2KB parameter page
  - 25 OTP pages
  - INTERNAL DATA MOVE by page
  - Promised golden block0
- **Package**
  - WSON8 8x6mm (TDFN8 8x6mm)
  - All Packages are RoHS Compliant and Halogen-free
- **Minimum 100,000 Program/Erase Cycles**
- **Data Retention: 10 years**

### 3. Packaging Type and Pin Configurations

FM25S01A is offered in a WSON8 8x6mm (TDFN8 8x6mm) as shown in Figure1. Package diagram and dimension are illustrated at the end of this datasheet.

Figure 1 Pad Assignments, WSON8 8x6mm (TDFN8 8x6mm)



#### 3.1. Pin Description

Table 1 Pin Description

PIN NO.	PIN NAME	I/O	FUNCTION
1	CS#	I	Chip Select Input
2	DO (DQ <sub>1</sub> )	I/O	Data Output (Data Input Output 1) <sup>(1)</sup>
3	WP# (DQ <sub>2</sub> )	I/O	Write Protect Input (Data Input Output 2) <sup>(2)</sup>
4	VSS		Ground
5	DI (DQ <sub>0</sub> )	I/O	Data Input (Data Input Output 0) <sup>(1)</sup>
6	CLK	I	Serial Clock Input
7	HOLD# (DQ <sub>3</sub> )	I/O	Hold Input (Data Input Output 3) <sup>(2)</sup>
8	VCC		Power Supply

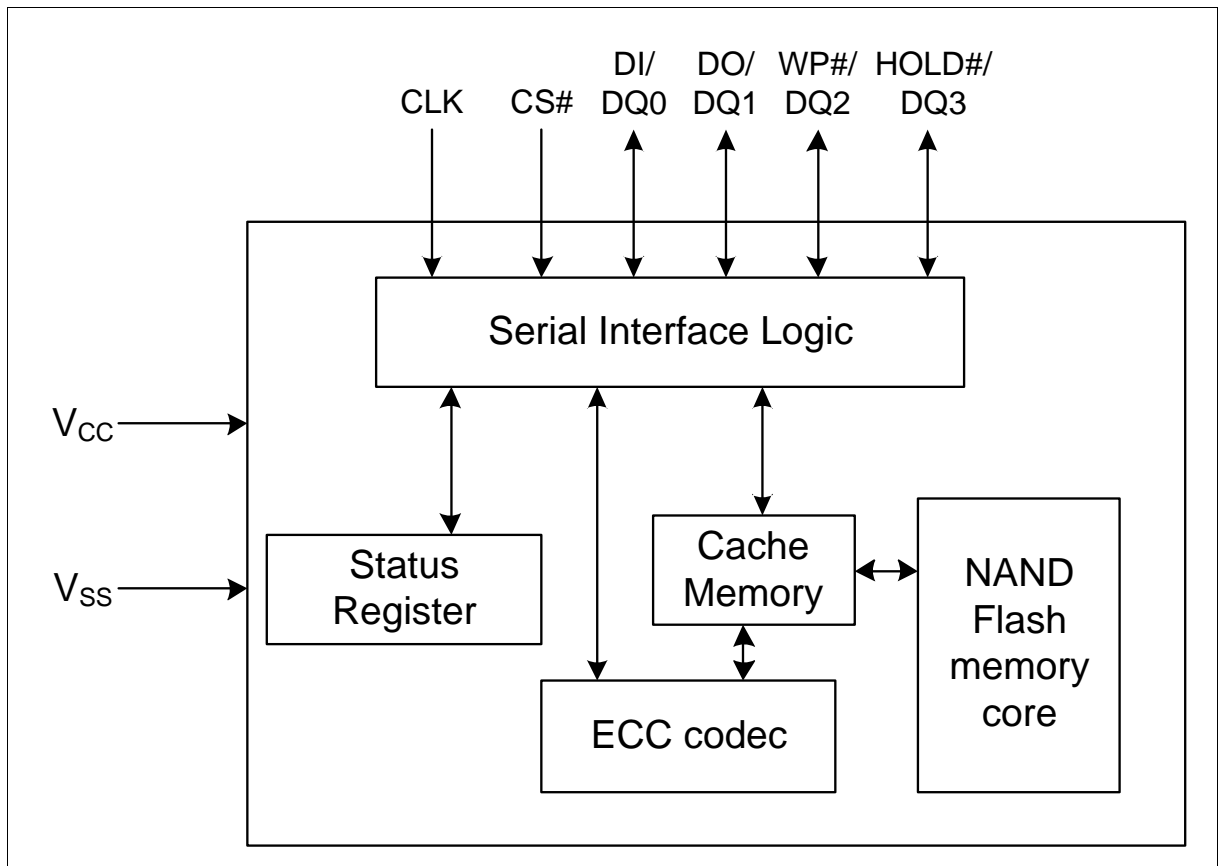
**Note:**

1 DQ<sub>0</sub> and DQ<sub>1</sub> are used for Dual SPI instructions.

2 DQ<sub>0</sub> – DQ<sub>3</sub> are used for Quad SPI instructions.

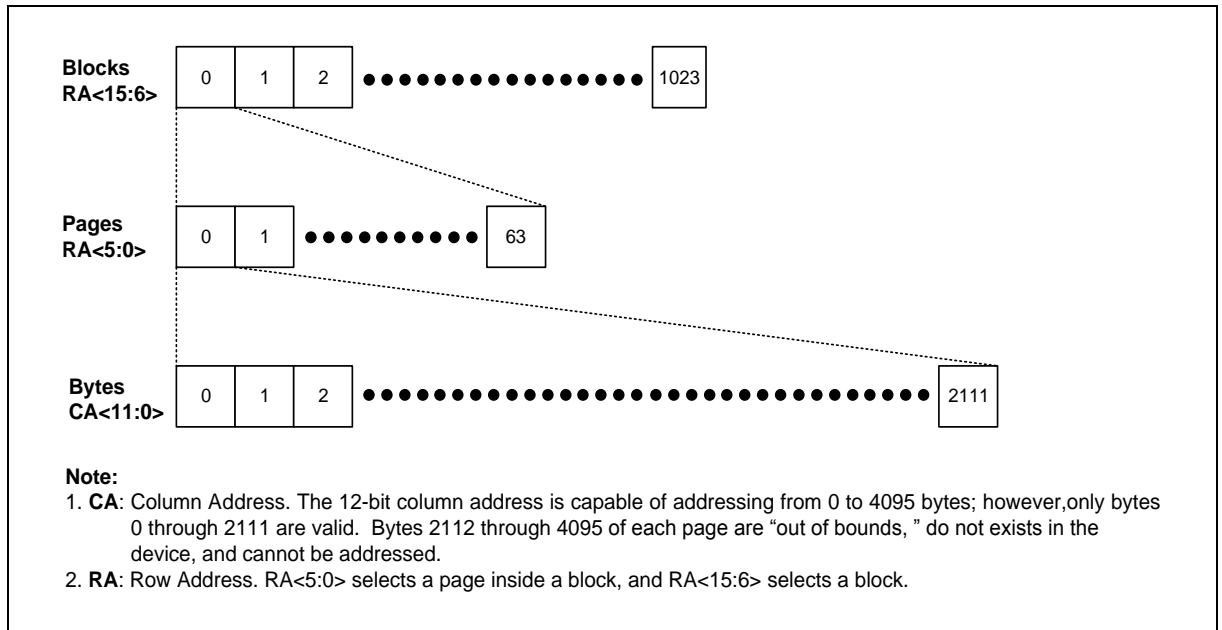
## 4. Block Diagram

Figure 2 SPI NAND Flash Memory Block Diagram



## 5. Memory Mapping

Figure 3 Memory Map

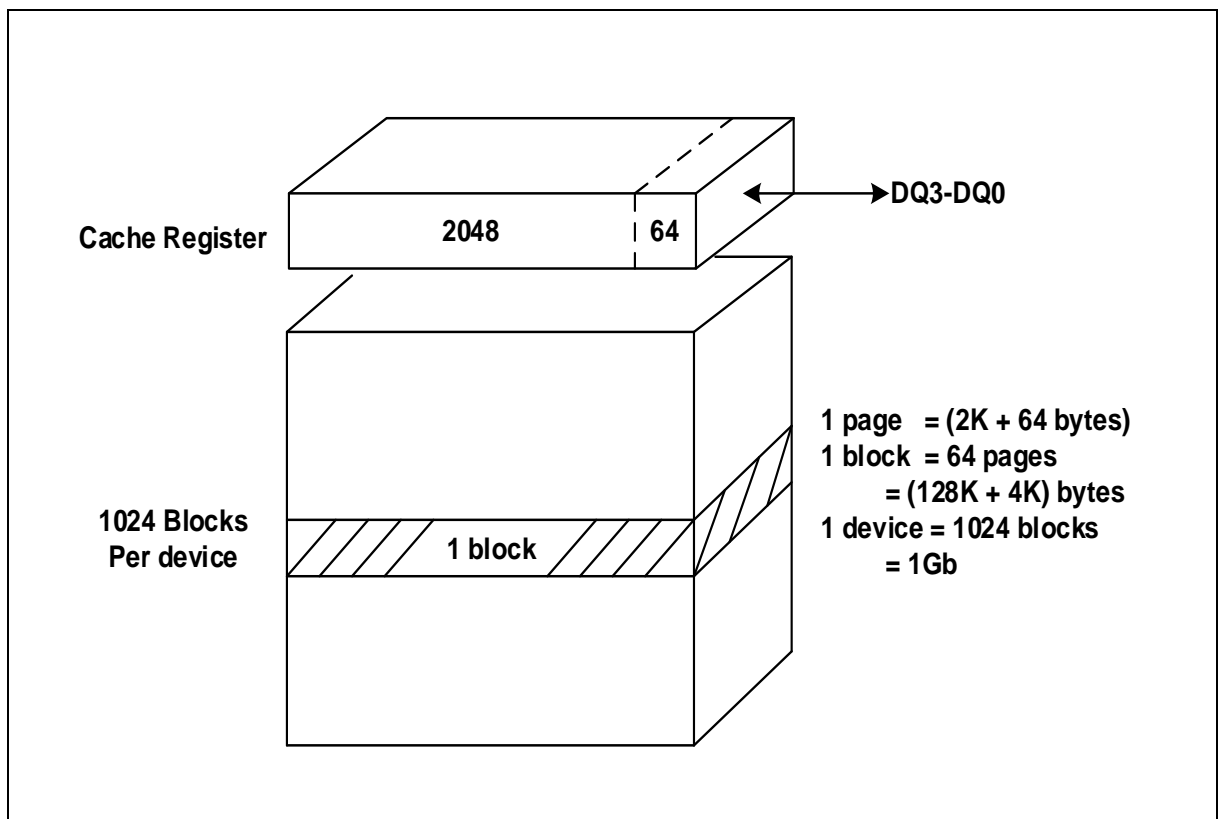


## 6. Array Organization

Table 2 Array Organization

Each device has	Each block has	Each page has	Unit
128M + 4M	128K + 4K	2K + 64	bytes
1024 x 64	64	-	Pages
1024	-	-	Blocks

Figure 4 Array Organization



## 7. Device Operations

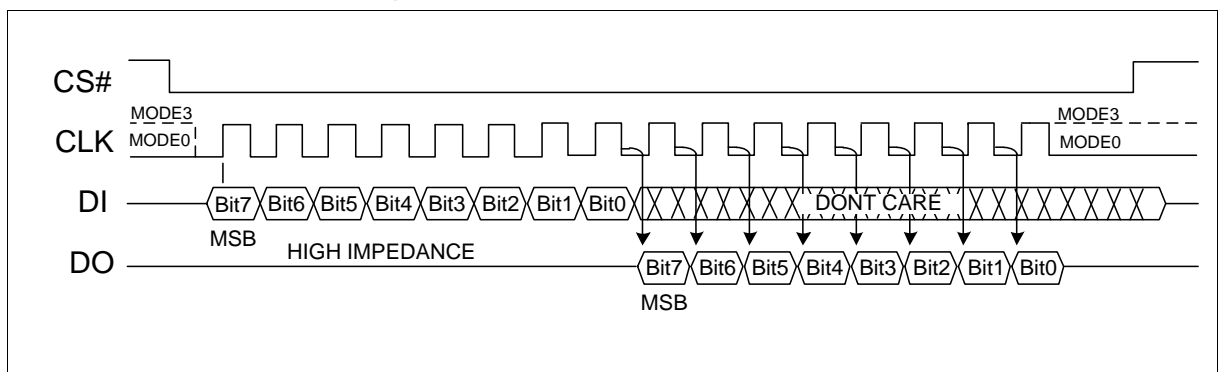
### 7.1. Single Data Rate (SDR)

#### 7.1.1. Standard SPI

The FM25S01A is accessed through an SPI compatible bus consisting of four signals: Serial Clock (CLK), Chip Select (CS#), Serial Data Input (DI) and Serial Data Output (DO). Standard SPI instructions use the DI input pin to serially write instructions, addresses or data to the device on the rising edge of CLK. The DO output pin is used to read data or status from the device on the falling edge of CLK.

SPI bus operation Mode 0 (0,0) and 3 (1,1) are supported. The primary difference between Mode 0 and Mode 3 concerns the normal state of the CLK signal when the SPI bus master is in standby and data is not being transferred to the Serial Flash. For Mode 0, the CLK signal is normally low on the falling and rising edges of CS#. For Mode 3, the CLK signal is normally high on the falling and rising edges of CS#.

Figure 5 SPI SDR Modes Supported



#### 7.1.2. Dual SPI

The FM25S01A supports Dual SPI operation when using the x2 and dual IO instructions. These instructions allow data to be transferred to or from the device at two times the rate of ordinary Serial Flash devices. When using Dual SPI instructions, the DI and DO pins become bidirectional I/O pins: DQ<sub>0</sub> and DQ<sub>1</sub>.

#### 7.1.3. Quad SPI

The FM25S01A supports Quad SPI operation when using the x4 and Quad IO instructions. These instructions allow data to be transferred to or from the device four times the rate of ordinary Serial Flash. When using Quad SPI instructions the DI and DO pins become bidirectional DQ<sub>0</sub> and DQ<sub>1</sub> and the WP # and HOLD# pins become DQ<sub>2</sub> and DQ<sub>3</sub> respectively.

## 7.2. CS#

The SPI Chip Select (CS#) pin enables and disables device operation. When CS# is high, the device is deselected and the Serial Data Output (DO, or DQ<sub>0</sub>, DQ<sub>1</sub>, DQ<sub>2</sub>, DQ<sub>3</sub>) pins are at high impedance. When deselected, the devices power consumption will be at standby levels unless an internal page read, erase, program or reset is in progress. When CS# is brought low, the device will be selected, power consumption will increase to active levels and instructions can be



written to and data read from the device. After power-up, CS# must transition from high to low before a new instruction will be accepted.

### 7.3. CLK

This input signal provides the synchronization reference for the SPI interface. Instructions, addresses, or data input are latched on the rising edge of the CLK signal. Data output changes after the falling edge of CLK.

### 7.4. Serial Input (DI) / DQ0

This input signal is used to transfer data serially into the device. It receives instructions, addresses, and data to be programmed. Values are latched on the rising edge of serial CLK clock signal.

DI becomes DQ0 - an input and output during Dual and Quad commands for receiving data to be programmed (values latched on rising edge of serial CLK clock signal) as well as shifting out data (on the falling edge of CLK).

### 7.5. Serial Output (DO) / DQ1

This output signal is used to transfer data serially out of the device. Data is shifted out on the falling edge of the serial CLK clock signal.

DO becomes DQ1 - an input and output during Dual and Quad commands for receiving data to be programmed (values latched on rising edge of serial CLK clock signal) as well as shifting out data (on the falling edge of CLK).

### 7.6. Write Protect (WP#) / DQ2

WP# is driven LOW to prevent writing the Feature Registers. The WPE bit in Protection Register controls the function of WP#, and the other bits in Register can protect a specific portion of array. When WPE=1, the device is in the Hardware-protection mode that WP# functions as a dedicated active low input pin for the Write Protect of the device. If WPE=1 and WP# goes LOW, the device will become READ-only. When WPE=0, the device is in the Software-protection mode that only Protection Register can be protected. WP# functions as a data I/O pin.

The WP# function is replaced by DQ2 for input and output during Quad mode for receiving data to be programmed (values are latched on rising edge of the CLK signal) as well as shifting out data (on the falling edge of CLK).

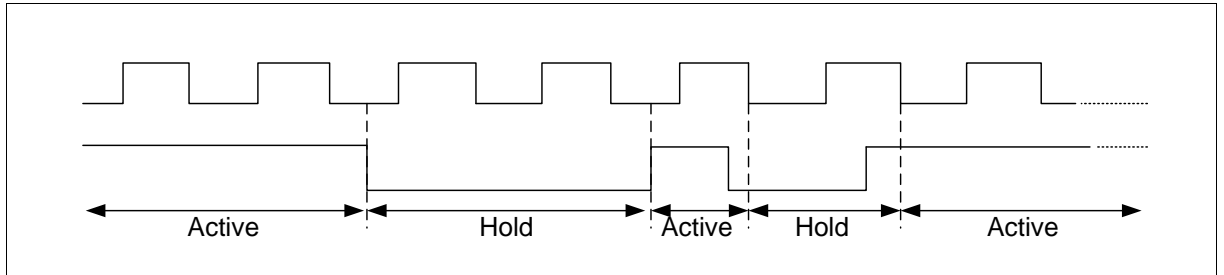
### 7.7. Hold (HOLD#) / DQ3

For Standard SPI and Dual SPI operations, the HOLD# signal allows the FM25S01A operation to be paused while it is actively selected (when CS# is low). The HOLD# function may be useful in cases where the SPI data and clock signals are shared with other devices. For example, consider if the page buffer was only partially written when a priority interrupt requires use of the SPI bus. In this case the HOLD# function can save the state of the instruction and the data in the buffer so programming can resume where it left off once the bus is available again.

To initiate a HOLD# condition, the device must be selected with CS# low. A HOLD# condition will activate on the falling edge of the HOLD# signal if the CLK signal is already low. If the CLK is not already low the HOLD# condition will activate after the next falling edge of CLK. The HOLD# condition will terminate on the rising edge of the HOLD# signal if the CLK signal is already low. If the CLK is not already low the HOLD# condition will terminate after the next falling edge of CLK. During a HOLD# condition, the Serial Output (DO) is high impedance, and Serial Input (DI) and Serial Clock (CLK) are ignored. The Chip Select (CS#) signal should be kept active (low) for the full duration of the HOLD# operation to avoid resetting the internal logic state of the device.

The HOLD# function is not available during the Quad mode. The Hold function is replaced by DQ3 for input and output during Quad mode for receiving addresses, and data to be programmed (values are latched on rising edge of the CLK signal) as well as shifting out data (on the falling edge of CLK).

**Figure 6 Hold Condition Waveform**

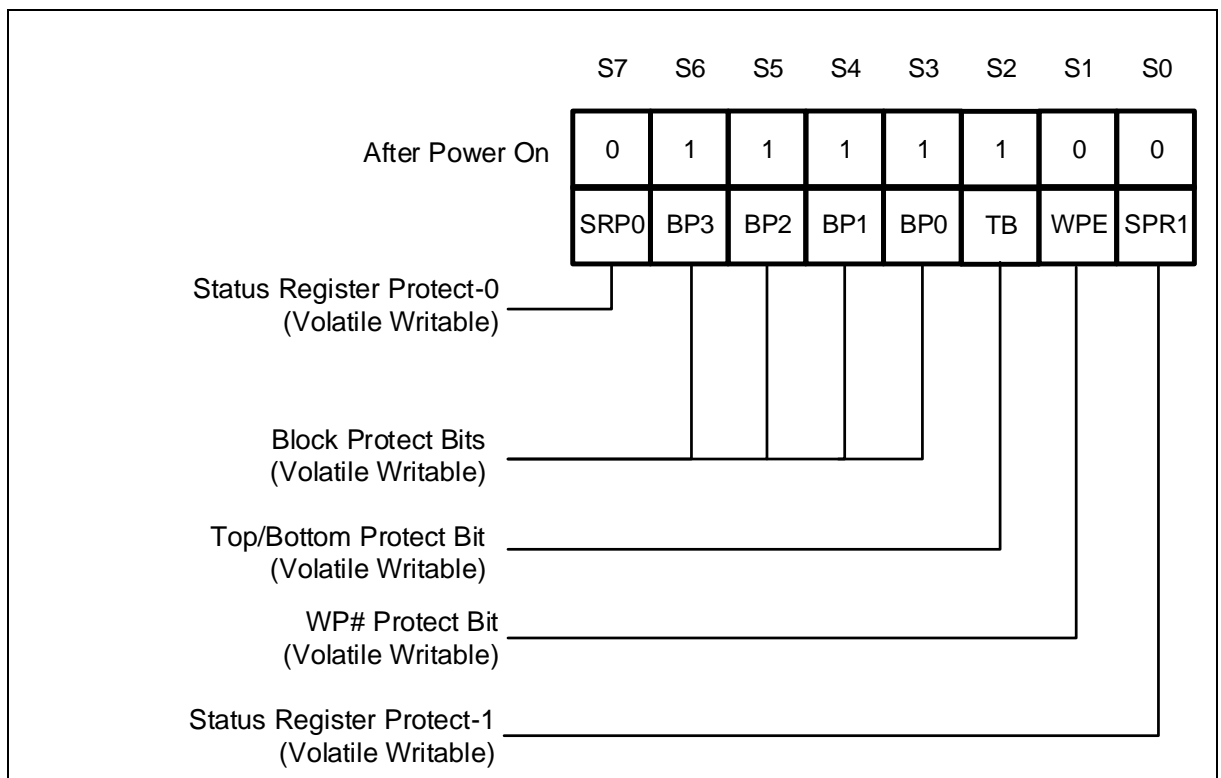


## 8. Status Register

Four Status Registers are provided for FM25S01A: Protection Register (SR-1), Configuration Register (SR-2), Status Register (SR-3) and Drive Register (SR-4). Each register is accessed by GET FEATURE and SET FEATURE commands combined with 1-Byte Register Address respectively.

### 8.1. Protection Register/Status Register-1(Volatile Writable)

Figure 7 Protection Register (Address A0h)



#### 8.1.1. Block Protection Bits (BP3, BP2, BP1, BP0, TB)

The Block Protect bits (BP3, BP2, BP1, BP0, TB) are volatile read/write bits in the status register-1 that provide Write Protection control and status. Block Protect bits can be set using the SET FEATURE Instruction. All, none or a portion of the memory array can be protected from Program and Erase instructions (See Status Register Memory Protection table). The default values for the Block Protection bits (BP3, BP2, BP1, BP0, TB) are 1 after power up to protect the entire array.

#### 8.1.2. Block Register Write Protection Bit (SRP1, SRP0, WPE)

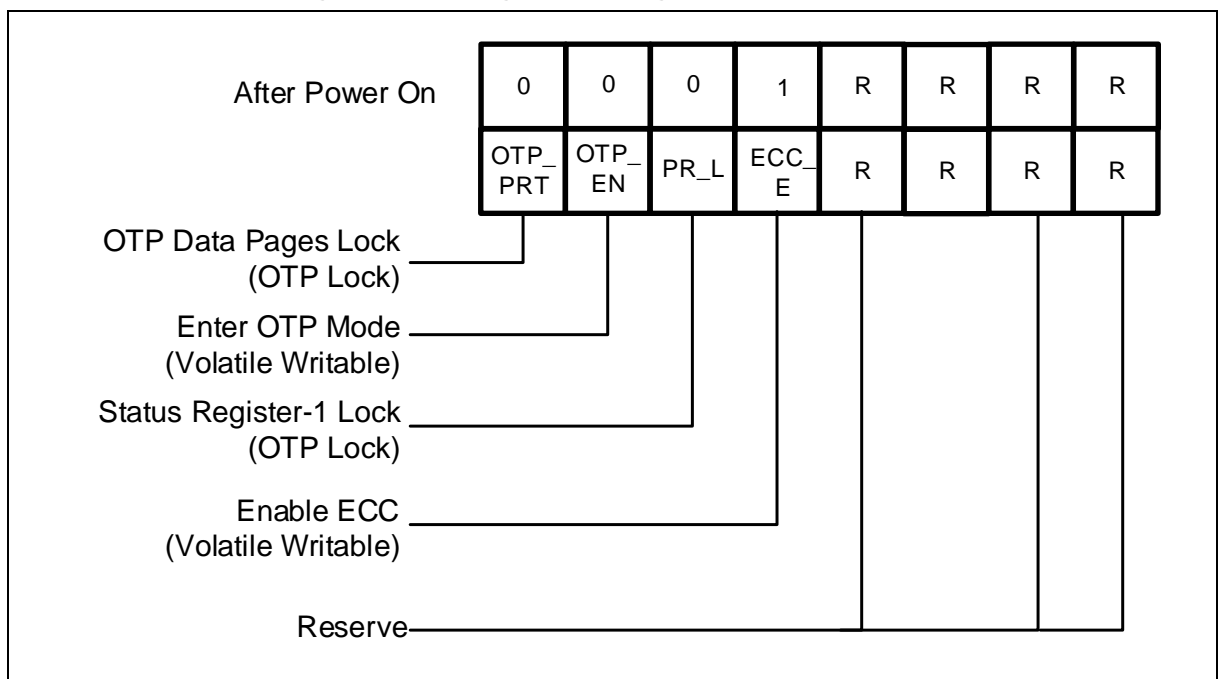
The block lock feature provides the ability to protect the entire device, or ranges of blocks, from the PROGRAM and ERASE operations. After power-up, the device is in the “locked” state, i.e., feature bit BP0, BP1, BP2, BP3, and TB are set to 1. To unlock all the blocks, or a range of blocks, the SET FEATURE command must be issued to alter the state of protection feature bit.

**Table 3 Protection Bits of Protection Register**

Software Protection (Controller, X4 Program/Read is enable)				
SRP1	SRP0	WPE	WP#	Description
0	0	0	X	No WP# functionality, and WP# pin will always function as DQ2
0	1	0	0	SR1 cannot be changed, and WP# pin will function as DQ2 for X4 operation
0	1	0	1	SR1 can be changed, and WP# pin will always function as DQ2
1	0	0	X	Power Lock Down SR1, and WP# pin will always function as DQ2
1	1	0	X	Set PR_L=1 is allowed, and SR1 is locked until next Power cycle, and WP# pin will always function as DQ2
Hardware Protection (System Circuit/PCB layout, X4 Program/Read is disable)				
SRP1	SRP0	WPE	WP#	Description
0	X	1	VCC	SR1 can be changed
1	0	1	VCC	Power Lock Down(1) SR1
1	1	1	VCC	Set PR_L=1 is allowed, and SR1 is locked until next Power cycle
X	X	1	GND	All Write operation are blocked, and entire device(Register, Array, and OTP area) is Read-only

**NOTE:**

- When SRP1=1 and SRP0=0, a cycle of power-down to power-up will change the state to SRP1=0 and SRP0=0.
- Once BP[3:0], TB, and WPE bits are set correctly, SRP0 and SRP1 should both be set to "1" as well to allow PR\_L bit being set to "1" to lock the protection in the SR1 (Protection Register) until next Power cycle.

**8.2. Configuration Register/Status Register-2****Figure 8 Configuration Register (Address B0h)**



### 8.2.1. One Time Program Lock Bit (OTP\_PRT) — Volatile Writable

In addition to the main memory array, FM25S01A also provides an OTP area for the system to store critical data that cannot be changed once it's locked. The OTP area consists of 30 pages of 2,112-Byte each. The default data in the OTP area are FFh. Only Program command can be issued to the OTP area to change the data from "1" to "0", and data is not reversible ("0" to "1") by the Erase command. Once the correct data is programmed in and verified, the system developer can set OTP\_PRT bit to 1, so that the entire OTP area will be locked to prevent further alteration to the data.

### 8.2.2. Enter OTP Access Mode Bit (OTP\_EN) — Volatile Writable

The OTP\_EN bit must be set to 1 in order to use the standard Program/Read commands to access the OTP area as well as to read the Unique ID/ Parameter Page information. The default value after power up is 0.

### 8.2.3. Protection Register Lock Bit (PR\_L) — Volatile Writable

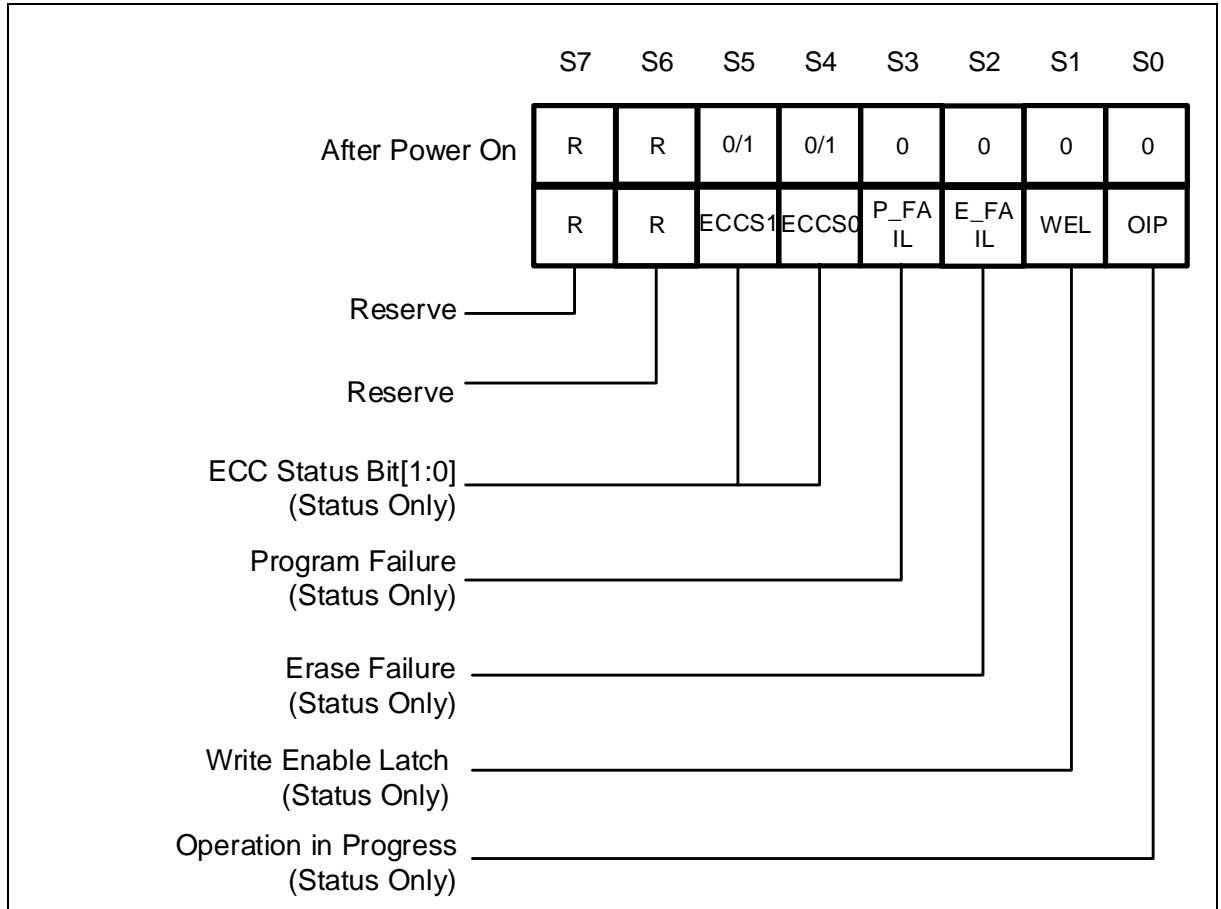
When SRP1=1 and SRP0=1, The PR\_L bit can be set to 1 to lock Protection Register lock. After that, Protection register (SR1) is locked until next Power cycle.

### 8.2.4. ECC Enable Bit (ECC\_E) — Volatile Writable

FM25S01A has a built-in ECC algorithm that can be used to preserve the data integrity. Internal ECC calculation is done during page programming, and the result is stored in the extra area for each page. During the data read operation, ECC engine will verify the data values according to the previously stored ECC information and to make necessary corrections if needed. The verification and correction status is indicated by the ECC Status Bits. ECC function is enabled by default when power on (ECC\_E=1), and it will not be reset to 0 by the Device Reset command.

### 8.3. Status Register-3

Figure 9 Status Register-3 (Address C0h)



#### 8.3.1. Cumulative ECC Status (ECCS1, ECCS0) —Status Only

ECC function is used in NAND flash memory to correct limited memory errors during read operations. The ECC Status Bits (ECCS1, ECCS0) should be checked after the completion of a Read operation to verify the data integrity. The ECC Status bits values are don't care if ECC\_E=0. These bits will be cleared to 0 after a RESET command.

After power-on, ECC status is set to reflect the contents of block 0, page 0.

Table 4 ECC Status Bits

ECC Status		Description
ECCS1	ECCS0	
0	0	No errors
0	1	1-bit error detected and corrected
1	0	2-bit or more than 2-bit errors detected and not corrected
1	1	Reserved

#### 8.3.2. Program/Erase Failure (P\_FAIL, E\_FAIL) —Status Only

The Program/Erase Failure Bits are used to indicate whether the internally-controlled Program/Erase operation was executed successfully or not. These bits will also be set respectively when the Program or Erase command is issued to a locked or protected memory or

OTP area. Both bits will be cleared at the beginning of the Program Execute or Block Erase instructions as well as the device RESET instruction.

### 8.3.3. Write Enable Latch (WEL) —Status Only

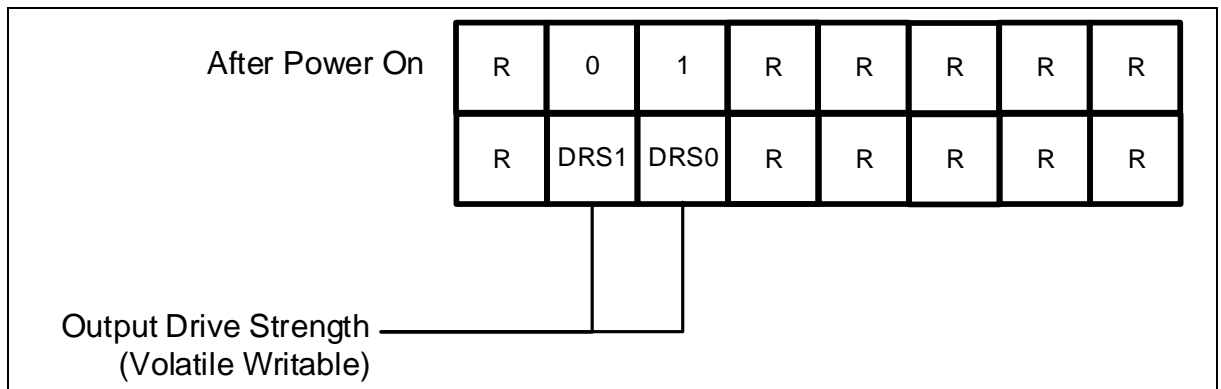
Write Enable Latch (WEL) is a read only bit in the status register that is set to 1 after executing a Write Enable Instruction. The WEL status bit is cleared to 0 when the device is write disabled. A write disable state occurs upon power-up or after any of the following instructions: Write Disable, Program Execute, Block Erase, Program Execute for OTP pages, and OTP locking.

### 8.3.4. Operation In Progress (OIP) —Status Only

OIP is a read only bit in the status register that is set to a 1 state when the device is powering up or executing a Page Data Read, Program Execute, Block Erase, Program Execute for OTP area, OTP Locking and RESET instruction. During this time the device will ignore further instructions except for the GET FEATURE, RESET and Read ID instructions. When the program, erase or page read instruction has completed, the OIP bit will be cleared to a 0 state indicating the device is ready for further instructions.

## 8.4. Output Drive Register

Figure 10 Output Drive Register (Address D0h)



### 8.4.1. Output Drive Strength (DRS1, DRS0)— Volatile Writable

Output Drive Strength bit can be used to adjust output PAD strength.

Table 5 Drive Strength Bits

DRS1	DRS0	Driver Strength
0	0	100%
0	1	75%
1	0	50%
1	1	25%

## 9. Command Definition

### 9.1. Command Set Tables

Table 6 Standard SPI Command Set

INSTRUCTION NAME	BYTE 1	BYTE 2	BYTE 3	BYTE 4	BYTE 5	BYTE N
WRITE ENABLE	06h					
WRITE DISABLE	04h					
GET FEATURE	0Fh	A7-A0	(D7-D0)			
SET FEATURE	1Fh	A7-A0	D7-D0			
PAGE READ	13h	A23-A16	A15-A8	A7-A0		
READ FROM CACHE	03h/0Bh	A15-A8 <sup>(2)</sup>	A7-A0	dummy	(D7-D0)	
READ ID	9Fh	dummy	(MID) <sup>(7)</sup>	(DID) <sup>(7)</sup>		
PROGRAM LOAD	02h	A15-A8 <sup>(6)</sup>	A7-A0	D7-D0	Next byte	Byte N
PROGRAM LOAD RANDOM DATA	84h	A15-A8 <sup>(6)</sup>	A7-A0	D7-D0	Next byte	Byte N
PROGRAM EXECUTE	10h	A23-A16	A15-A8	A7-A0		
BLOCK ERASE	D8h	A23-A16	A15-A8	A7-A0		
RESET	FFh					

Table 7 Dual SPI Command Set

INSTRUCTION NAME	BYTE 1	BYTE 2	BYTE 3	BYTE 4	BYTE 5	BYTE N
READ FROM CACHE x 2	3Bh	A15-A8 <sup>(2)</sup>	A7-A0	dummy	(D7-D0)x2	
READ FROM CACHE DUAL IO	BBh	A15-A0 <sup>(3)</sup>	dummy <sup>(4)</sup>	(D7-D0)x2		

Table 8 Quad SPI Command Set

INSTRUCTION NAME	BYTE 1	BYTE 2	BYTE 3	BYTE 4	BYTE 5	BYTE N
READ FROM CACHE x4	6Bh	A15-A8 <sup>(2)</sup>	A7-A0	dummy	(D7-D0)x4	
READ FROM CACHE QUAD IO	EBh	A15-A0 <sup>(5)</sup>	(D7-D0)x4			
PROGRAM LOAD x4	32h	A15-A8 <sup>(6)</sup>	A7-A0	(D7-D0)x4	Next byte	Byte N
PROGRAM LOAD RANDOM DATA x4	34h	A15-A8 <sup>(6)</sup>	A7-A0	(D7-D0)x4	Next byte	Byte N

**Notes:**

- Data bytes are shifted with Most Significant Bit first. Byte fields with data in parenthesis "( )" indicate data output from the device on either 1, 2 or 4 DQ pins.
- The x8 clock = dummy<3:0>, A11-A8
- The x8 clock = dummy<3:0>, A11-A0
- The x8 clock = dummy<7:0>, D7-D0
- The x8 clock = dummy<3:0>, A11-A0, dummy<15:0>
- The x8 clock = dummy<3:0>, A11-A8
- MID is Manufacture ID(A1h for FMSH), DID is Device ID(E4h for current device)



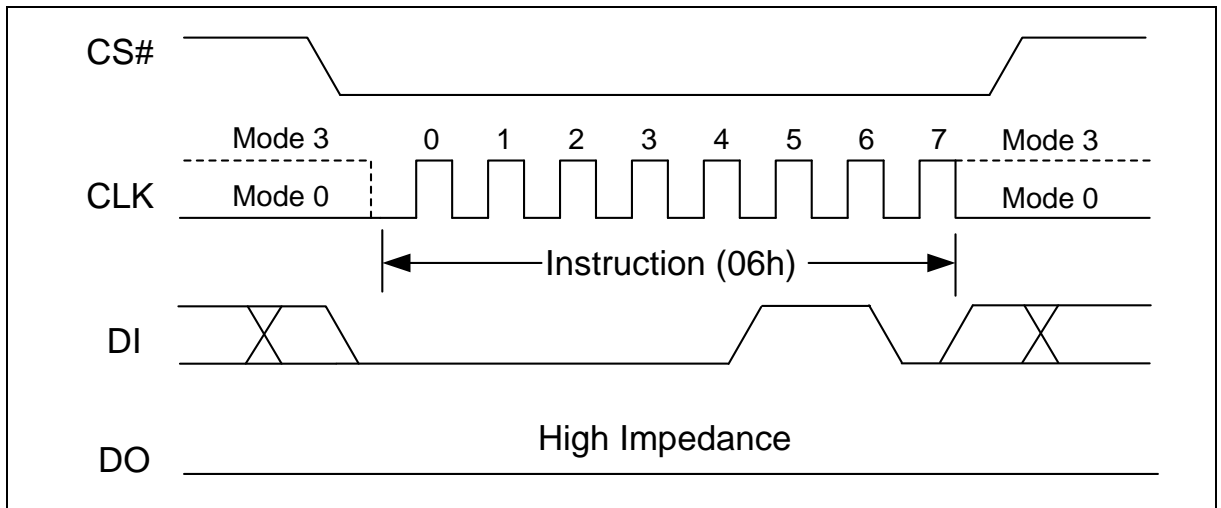
## 9.2. WRITE operation

### 9.2.1. WRITE ENABLE (WREN) (06h)

The WRITE ENABLE (WREN) command sets the WEL bit in the status register to 1. The WEL bit must be set prior to following operations that changes the contents of the memory array:

- PAGE PROGRAM
- OTP PROGRAM
- OTP LOCK
- BLOCK ERASE

Figure 11 WRITE ENABLE (06h) Timing

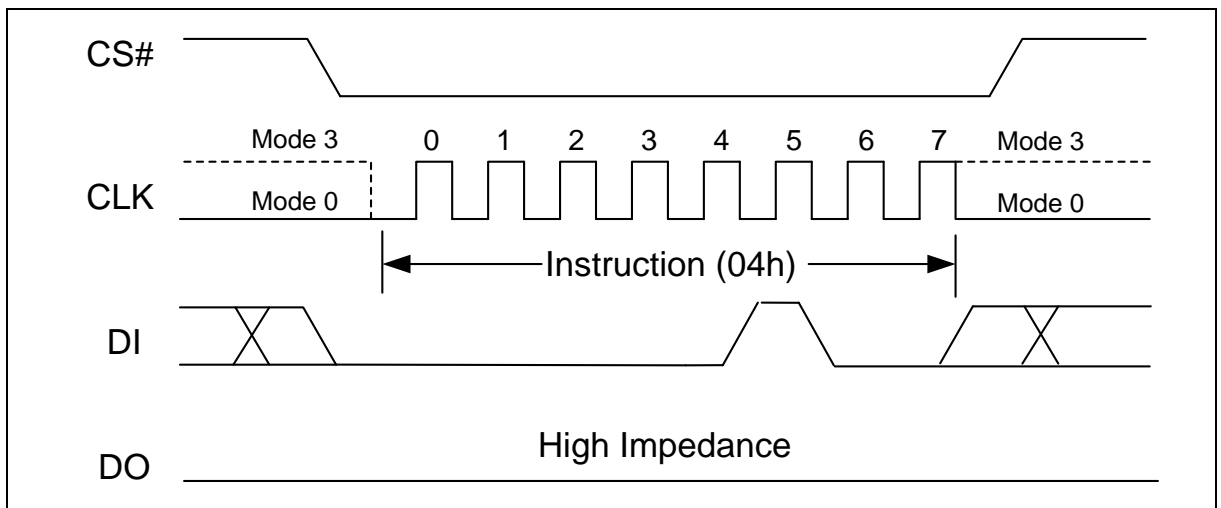


### 9.2.2. WRITE DISABLE (WRDI) (04h)

The WRITE DISABLE (WRDI) command resets the WEL bit in the status register to 0. The WEL bit is automatically reset after Power-up and upon completion of the following operations:

- PAGE PROGRAM
- OTP PROGRAM
- OTP LOCK
- BLOCK ERASE

Figure 12 WRITE DISABLE (04h) Timing



## 9.3. Feature Operation

### 9.3.1. GET FEATURE (0Fh) and SET FEATURE (1Fh)

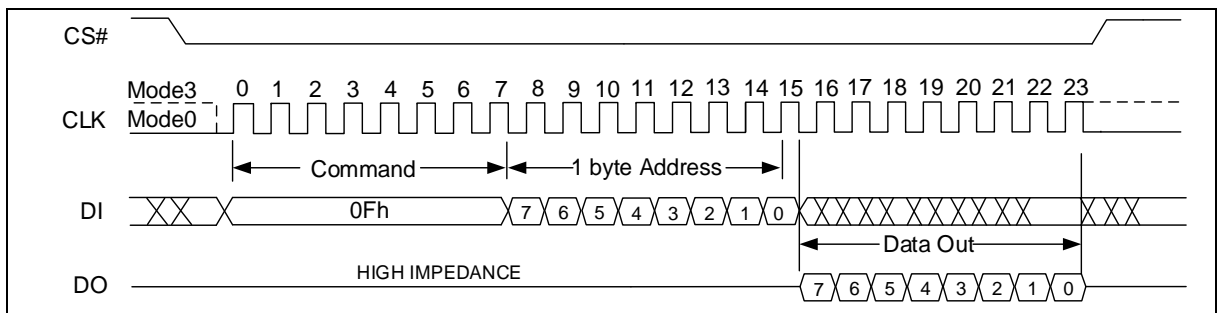
The GET FEATURE (0Fh) and SET FEATURE (1Fh) commands are used to alter the device behavior from the default power-on behavior. These commands use a 1-byte feature address to determine which feature is to be read or modified. Features such as OTP and block protection can be enabled or disabled by setting specific bits in feature address A0h and B0h (shown the following table). The status register is mostly read, except WEL, which is writable bit with the WREN (06h) command.

When a feature is set, it remains active until the device is power cycled or the feature is written to. Unless otherwise specified in the Status Register section, once the device is set, it remains set, even if a RESET (FFh) command is issued.

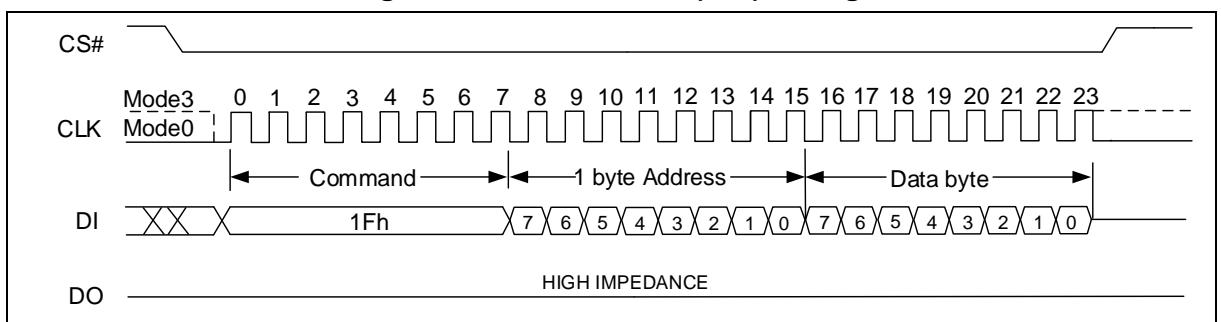
**Table 9 Features Setting**

Register	Address	Data Bits							
		7	6	5	4	3	2	1	0
SR-1	A0h	SRP0	BP3	BP2	BP1	BP0	TB	WPE	SRP1
SR-2	B0h	OTP_PRT	OTP_EN	PR_L	ECC_E	Reserved	Reserved	Reserved	Reserved
SR-3	C0h	Reserved	Reserved	ECCS1	ECCS0	P_FAIL	E_FAIL	WEL	OIP
SR-4	D0h	Reserved	DRS1	DRS1	Reserved	Reserved	Reserved	Reserved	Reserved

**Figure 13 GET FEATURE (0Fh) Timing**



**Figure 14 SET FEATURE (1Fh) Timing**



## 9.4. READ Operation

### 9.4.1. PAGE READ

The PAGE READ (13h) command transfers the data from the NAND Flash array to the cache register. The command sequence is follows:

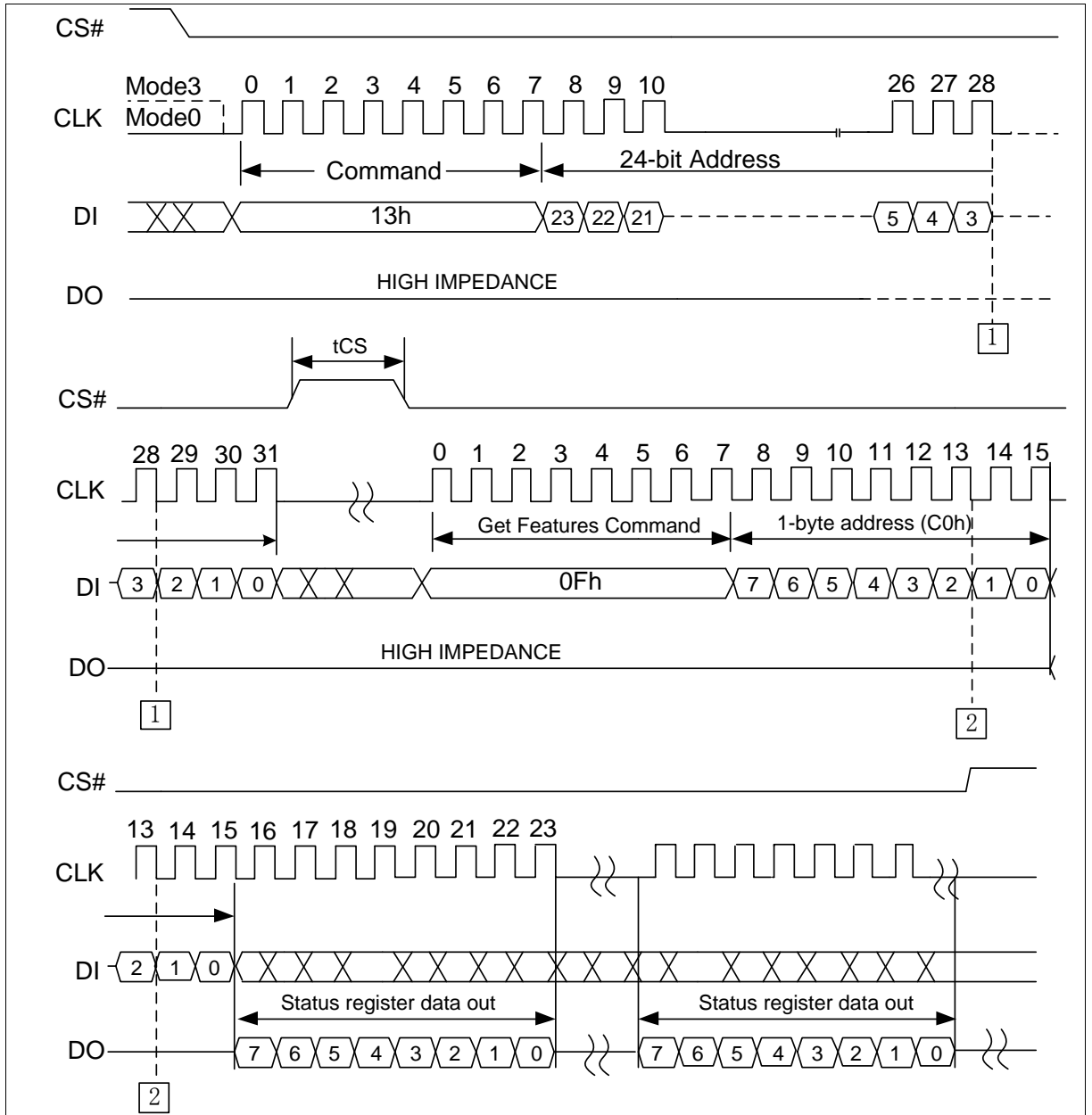
- 13h (PAGE READ TO CACHE)
- 0Fh (GET FEATURE command to read the status)
- READ FROM CACHE Operation
  - 0Bh or 03h (READ FROM CACHE)
  - 3Bh (READ FROM CACHE x2)
  - 6Bh (READ FROM CACHE x4)
  - BBh (READ FROM CACHE DUAL IO)
  - EBh (READ FROM CACHE QUAD IO)

The PAGE READ command requires a 24-bit address consisting of 8 dummy bits followed by a 16-bit block/page address. After the block/page addresses are registered, the device starts the transfer from the main array to the cache register, and is busy for  $t_{RD}$  time. During this time, the GET FEATURE (0Fh) command can be issued to monitor the status of the operation (refer to the Status Register section). Following a status of successful completion, the READ FROM CACHE (03h/0Bh/3Bh/6Bh/BBh/EBh) command must be issued in order to read the data out of the cache.

The READ FROM CACHE command requires 4 dummy bits, followed by 12-bit column address for the starting byte address. The starting byte address must be in 0 to 2111.

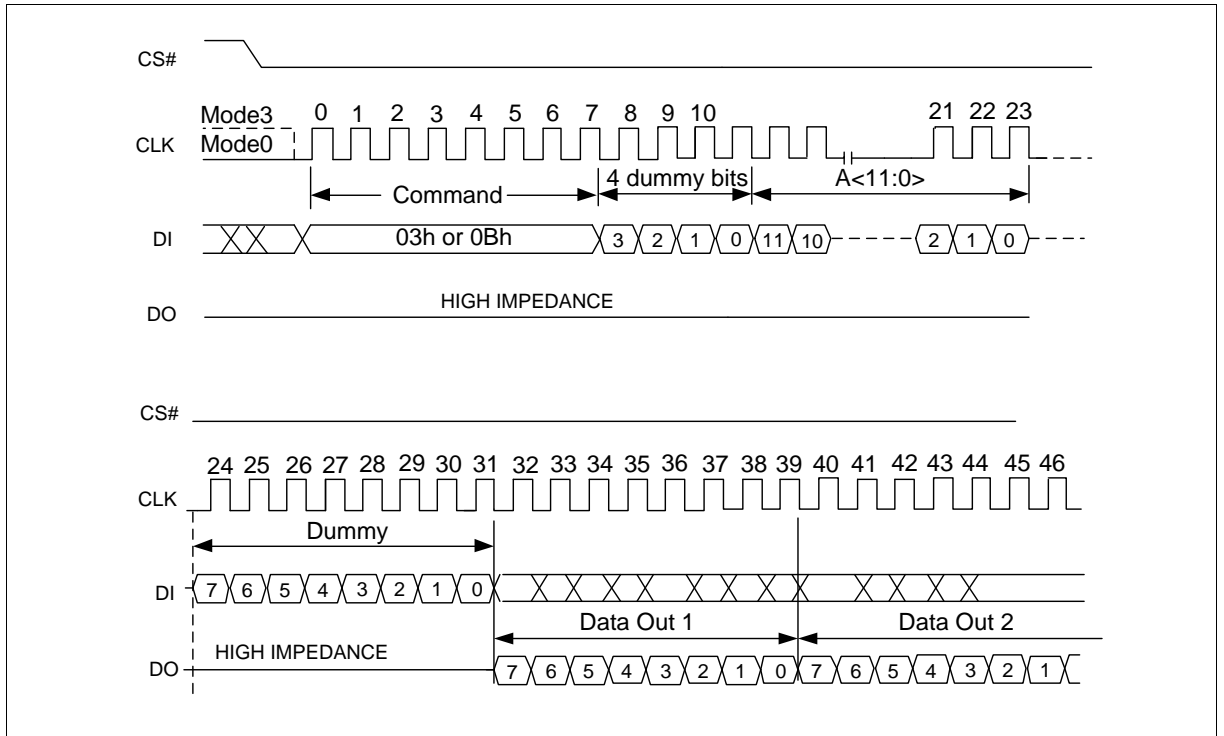
## 9.4.2. PAGE READ TO CACHE (13h)

Figure 15 Page Read to Cache (13h) Timing



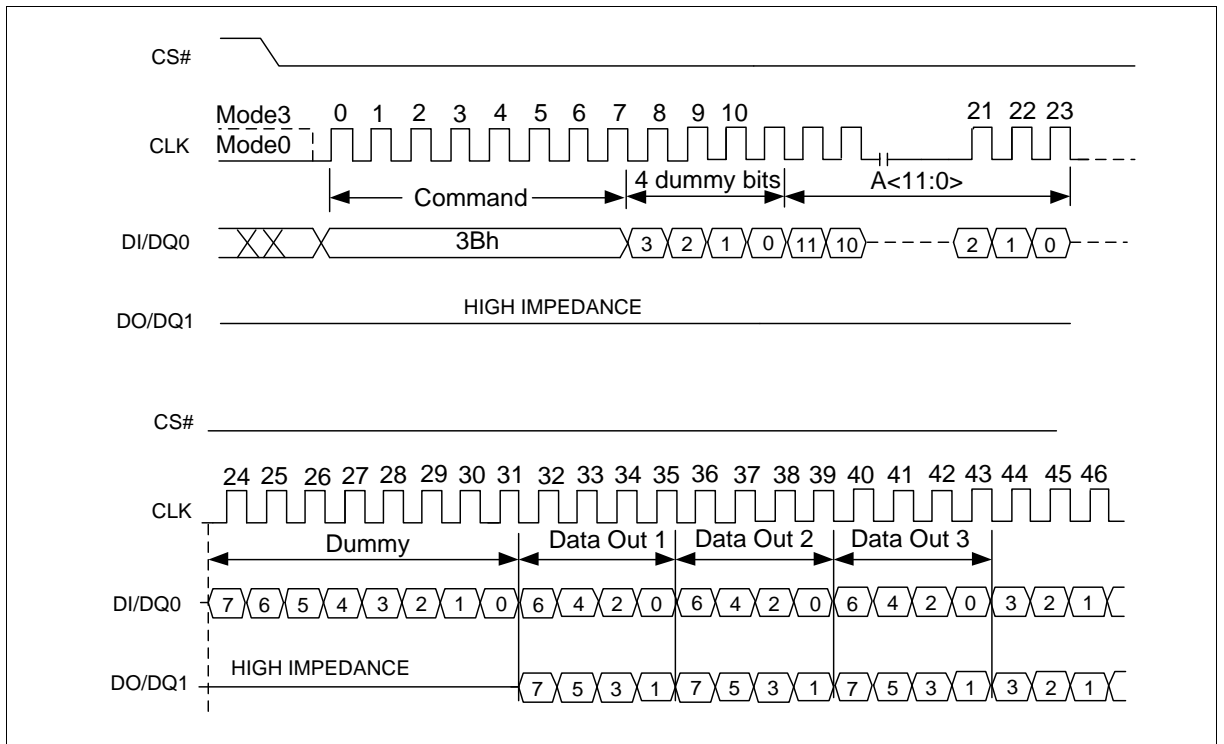
### 9.4.3. READ FROM CACHE (03h/0Bh)

Figure 16 READ FROM CACHE (03h / 0Bh) Timing



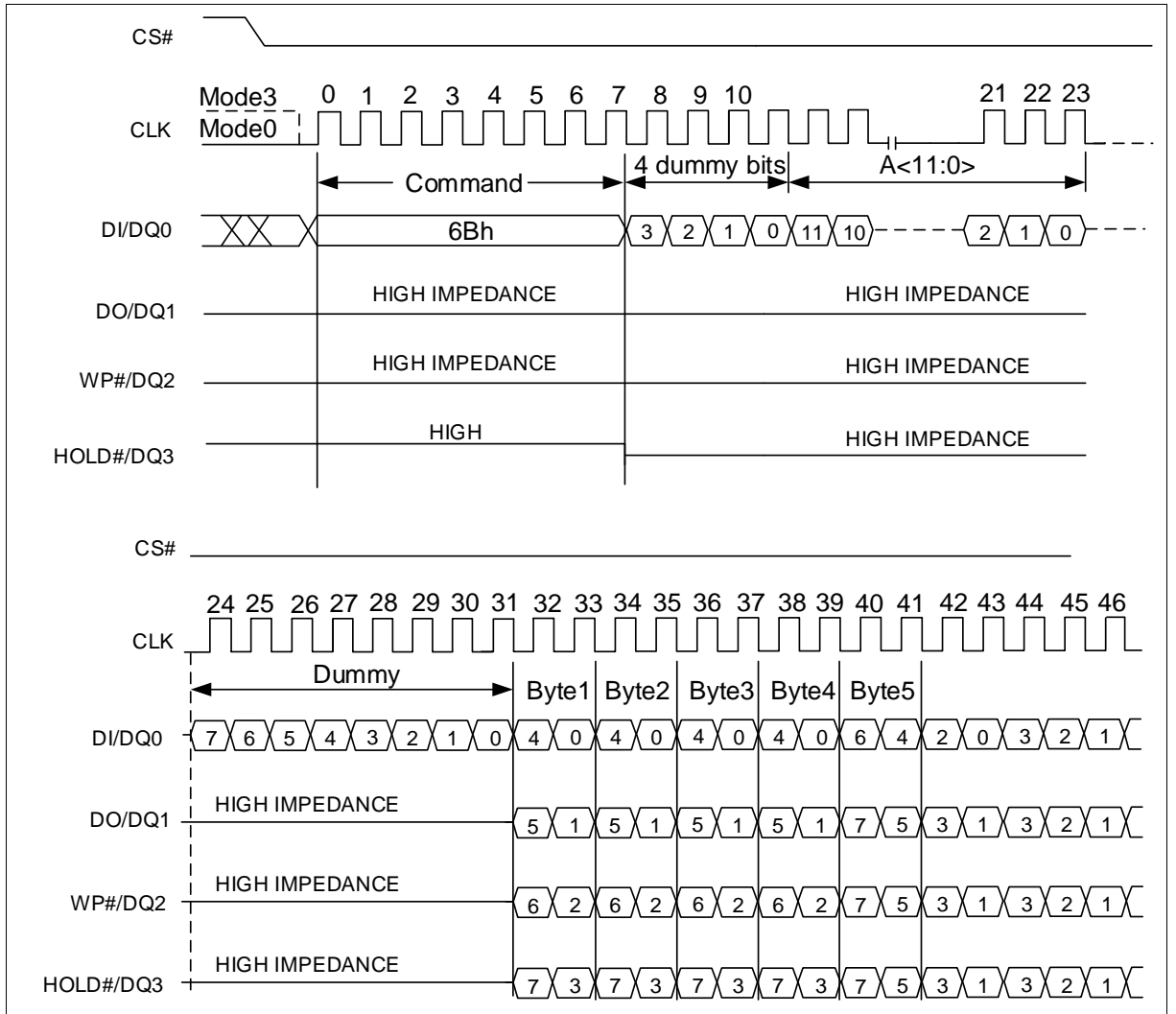
### 9.4.4. READ FROM CACHE x2 (3Bh)

Figure 17 READ FROM CACHE x2 (3Bh) Timing



### 9.4.5. READ FROM CACHE x4 (6Bh)

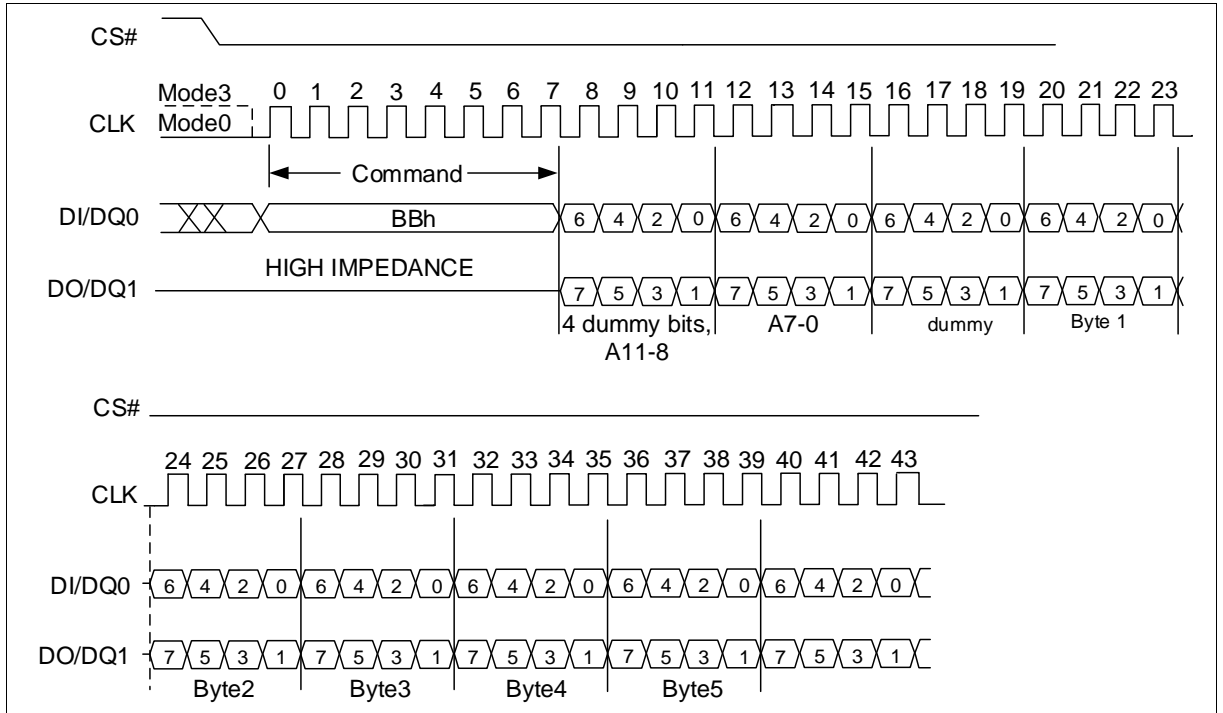
Figure 18 READ FROM CACHE x4 (6Bh) Timing



### 9.4.6. READ FROM CACHE DUAL IO (BBh)

The READ FROM CACHE DUAL IO command is similar to the READ FROM CACHE x2 command except that dummy bits, 12-bit column address and dummy bits are input through two pins DQ<sub>0</sub>, DQ<sub>1</sub>.

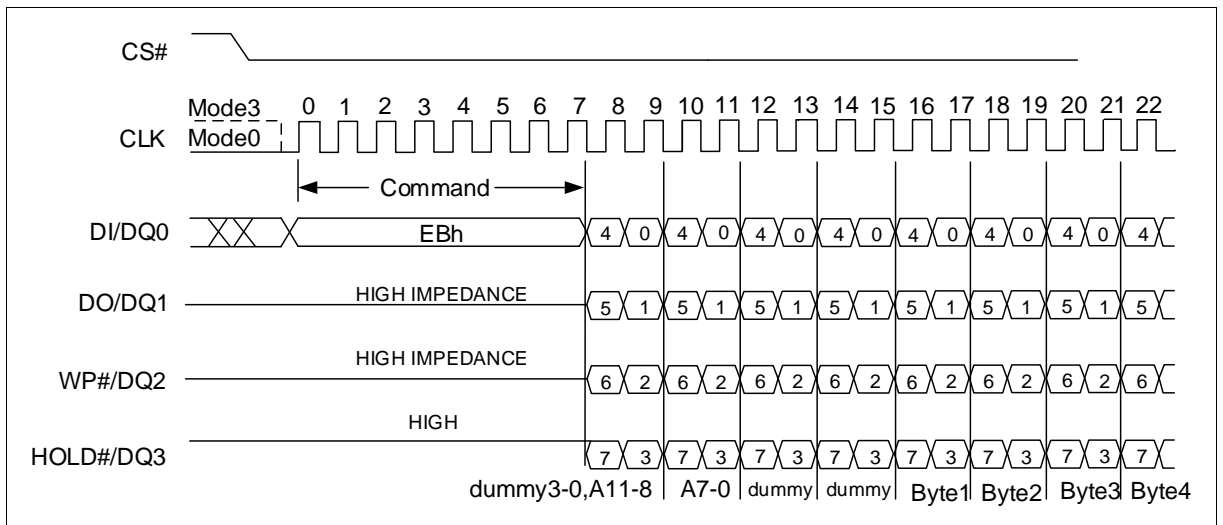
Figure 19 READ FROM CACHE DUAL IO (BBh) Timing



### 9.4.7. READ FROM CACHE QUAD IO (EBh)

The READ FROM CACHE QUAD IO command is similar to the READ FROM CACHE x4 command except that dummy bits, 12-bit column address and dummy bits are input through four pins DQ<sub>0</sub>, DQ<sub>1</sub>, DQ<sub>2</sub> and DQ<sub>3</sub>.

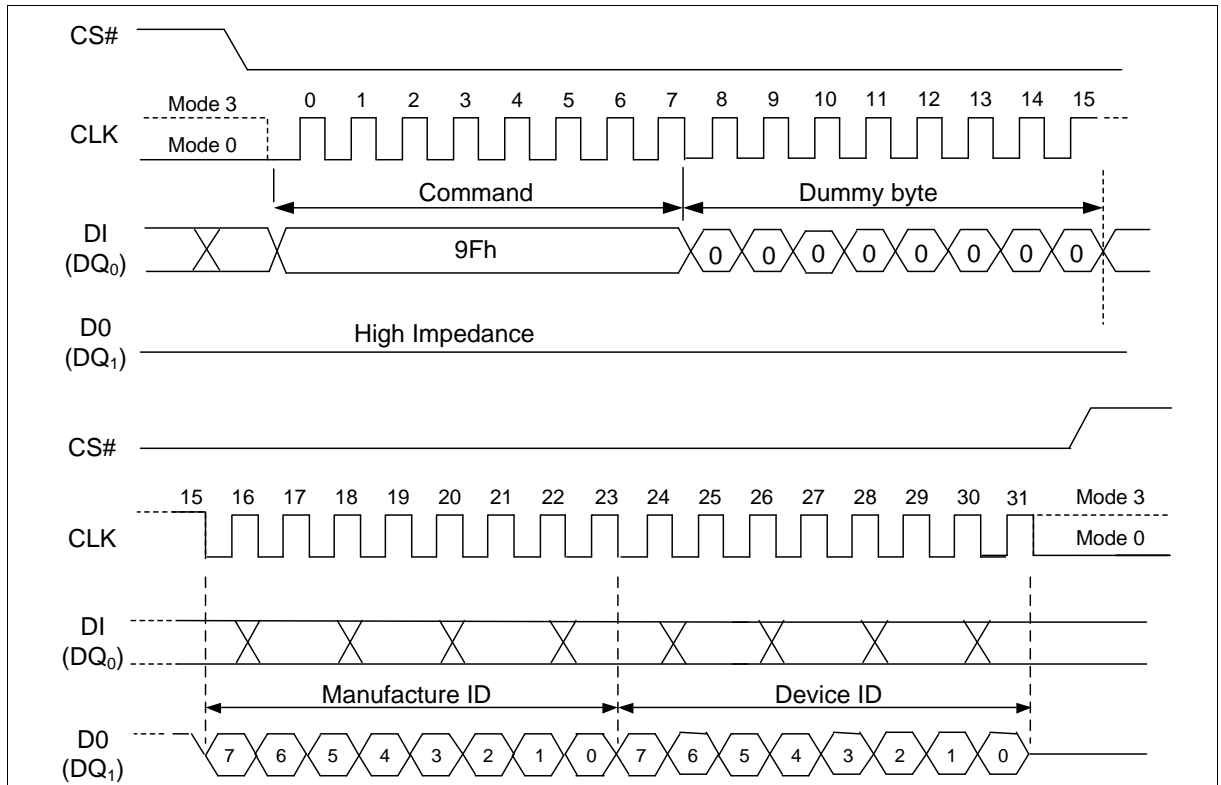
Figure 20 READ FROM CACHE QUAD IO (EBh) Timing



## 9.4.8. READ ID (9Fh)

The READ ID command is used to read the 2 bytes of identifier code programmed into the NAND Flash device. The READ ID command reads a 2-byte that includes the Manufacturer ID and the device configuration.

Figure 21 READ ID (9Fh) Timing



## 9.5. PROGRAM Operation

The PAGE PROGRAM operation sequence programs 1 byte to 2112 bytes of data within a page. The page program sequence is as follows:

- 02H (PROGRAM LOAD)/32H (PROGRAM LOAD x4)
- 06H (WRITE ENABLE)
- 10H (PROGRAM EXECUTE)
- 0FH (GET FEATURE command to read the status)

The 1<sup>st</sup> step is to issue a PROGRAM LOAD (02H/32H) command. PROGRAM LOAD consists of an 8-bit Op code, followed by 4 dummy bits and a 12-bit column address, then the data bytes to be programmed. The data bytes are loaded into a cache register which is 2112 bytes long. If more than 2112 bytes are loaded, then those additional bytes are ignored by the cache register. The command sequence ends when CS# goes from LOW to HIGH. Figure 22 shows the PROGRAM LOAD operation.

The 2<sup>nd</sup> step, prior to performing the PROGRAM EXECUTE operation, is to issue a WRITE ENABLE (06H) command. As with any command that changes the memory contents, the WRITE ENABLE must be executed in order to set the WEL bit. If this command is not issued, then the rest of the program sequence is ignored.

The 3<sup>rd</sup> step is to issue a PROGRAM EXECUTE (10h) command to initiate the transfer of data from the cache register to the main array. PROGRAM EXECUTE consists of an 8-bit Op code, followed by a 24-bit address (8 dummy bits and an 16-bit page/block address). After the page/block address is registered, the memory device starts the transfer from the cache register to



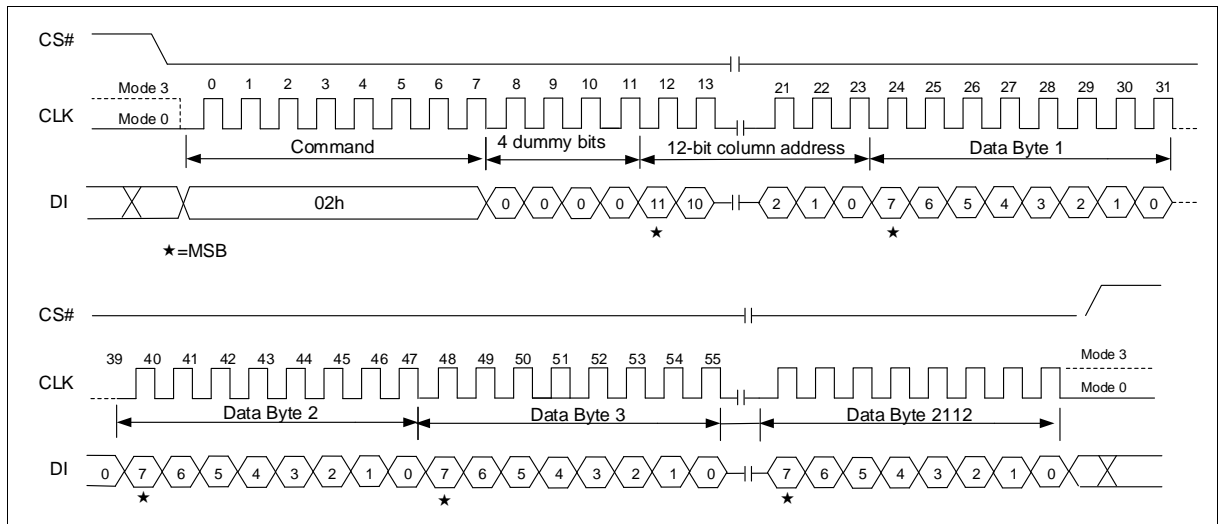
the main array, and is busy for  $t_{\text{PROG}}$  time. This operation is shown in Figure 24.

During this busy time, the status register can be polled to monitor the status of the operation (refer to the Status Register section). When the operation completes successfully, the next series of data can be loaded with the PROGRAM LOAD command.

**Note:** The number of consecutive partial page programming operations (NOP) within the same page must not exceed 4. In addition, pages must be sequentially programmed within a block.

### 9.5.1. PROGRAM LOAD (02h)

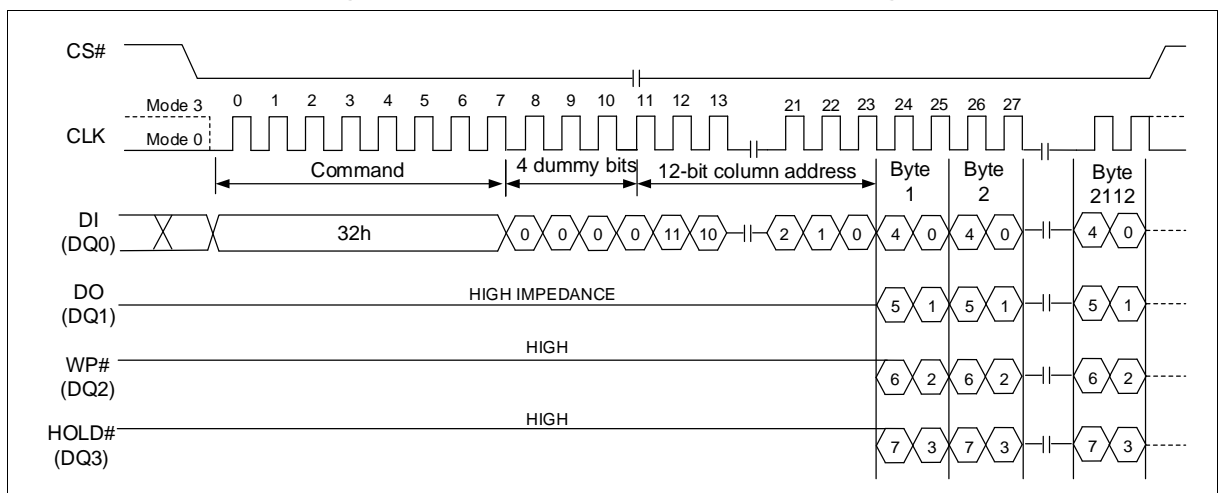
Figure 22 PROGRAM LOAD (02h) Timing



### 9.5.2. PROGRAM LOAD x4 (32h)

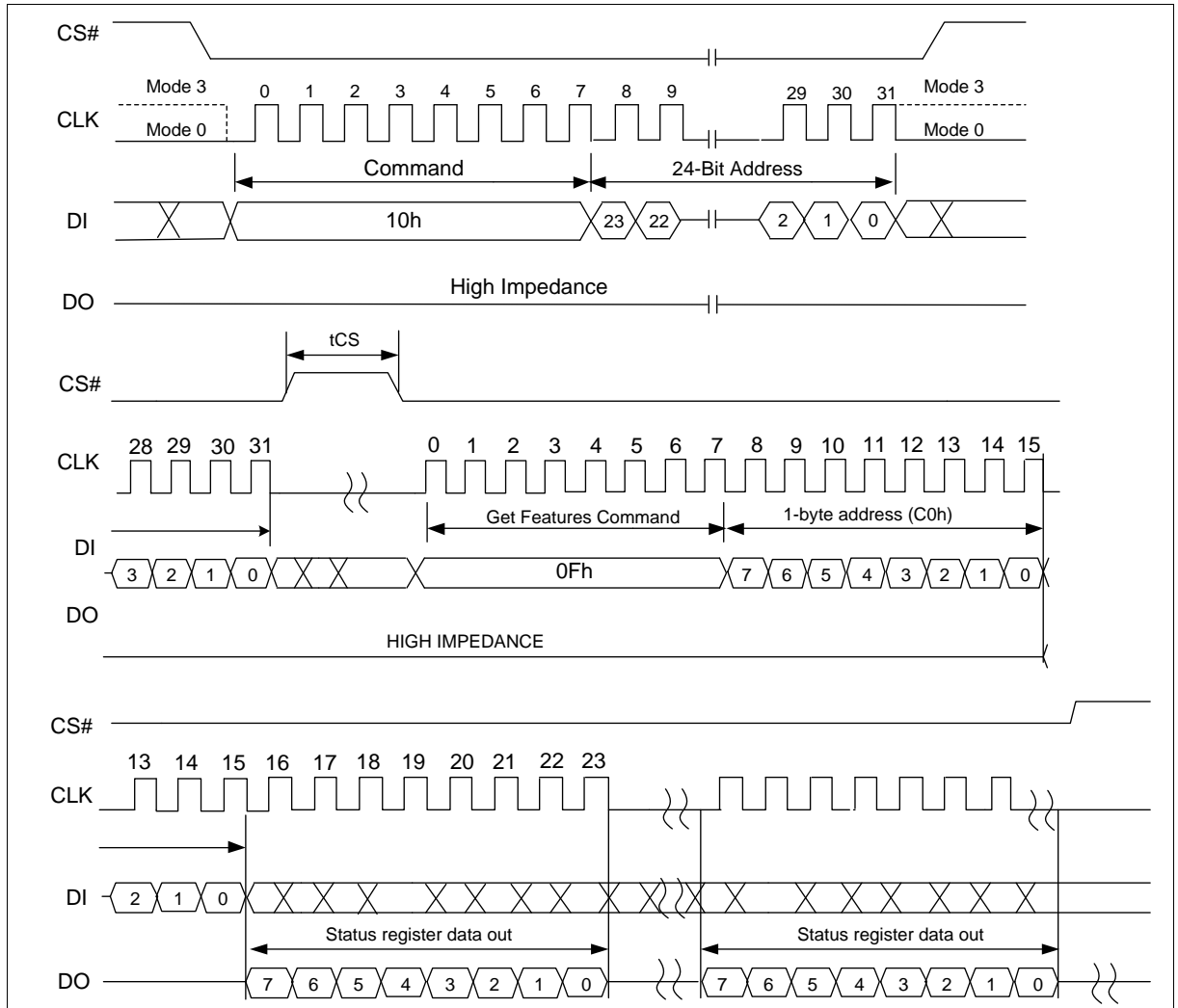
The PROGRAM LOAD x4 command (32H) is similar to the PROGRAM LOAD command (02H) but with the capability to input the data bytes by four pins: DQ0, DQ1, DQ2, and DQ3. The command sequence is shown below. The WPE bit of feature (A0[1]) must be reset to “0” to enable the PROGRAM LOAD x4 command.

Figure 23 PROGRAM LOAD x4 (32h) Timing



### 9.5.3. PROGRAM EXECUTE (PE) (10h)

Figure 24 PROGRAM EXECUTE (10h) Timing



### 9.5.4. Random Data Program

The command sequence is as follows:

- 84h (PROGRAM LOAD RANDOM DATA x1) / 34h (x4)
- 06H (WRITE ENABLE)
- 10H (PROGRAM EXECUTE)
- 0FH (GET FEATURE command to read the status)

The random data program operation sequence programs or replaces data in a page with existing data. PROGRAM LOAD RANDOM DATA command requires 16-bit address with 4 dummy bits and a 12-bit column address. New data is loaded in the column address provided. If the random data is not sequential, then another PROGRAM LOAD RANDOM DATA command must be issued with a new column address. After the data is loaded, PROGRAM EXECUTE command can be issued to start the programming operation.



## 9.5.8. INTERNAL DATE MOVE

The INTERNAL DATA MOVE command sequence programs or replaces data in a page with existing data. The INTERNAL DATA MOVE command sequence is as follows:

- 13H (PAGE READ TO CACHE)
- 84H/34H (PROGRAM LOAD RANDOM DATA : Optional)
- 06H (WRITE ENABLE)
- 10H (PROGRAM EXECUTE)
- 0FH (GET FEATURE command to read the status)

Prior to performing an INTERNAL DATA MOVE operation, the target page content must be read out into the cache register by issuing a PAGE READ (13H) command. The PROGRAM LOAD RANDOM DATA (84H/34H) command can be issued, if user wants to update bytes of data in the page. This command consists of an 8-bit Op code, followed by 4 dummy bits and a 12-bit column address. New data is loaded in the 12-bit column address. If the RANDOM DATA is not sequential, another PROGRAM LOAD RANDOM DATA (84H/34H) command must be issued with the new column address. After the data is loaded, the WRITE ENABLE command must be issued, then a PROGRAM EXECUTE (10H) command can be issued to start the programming operation.

## 9.6. ERASE Operation

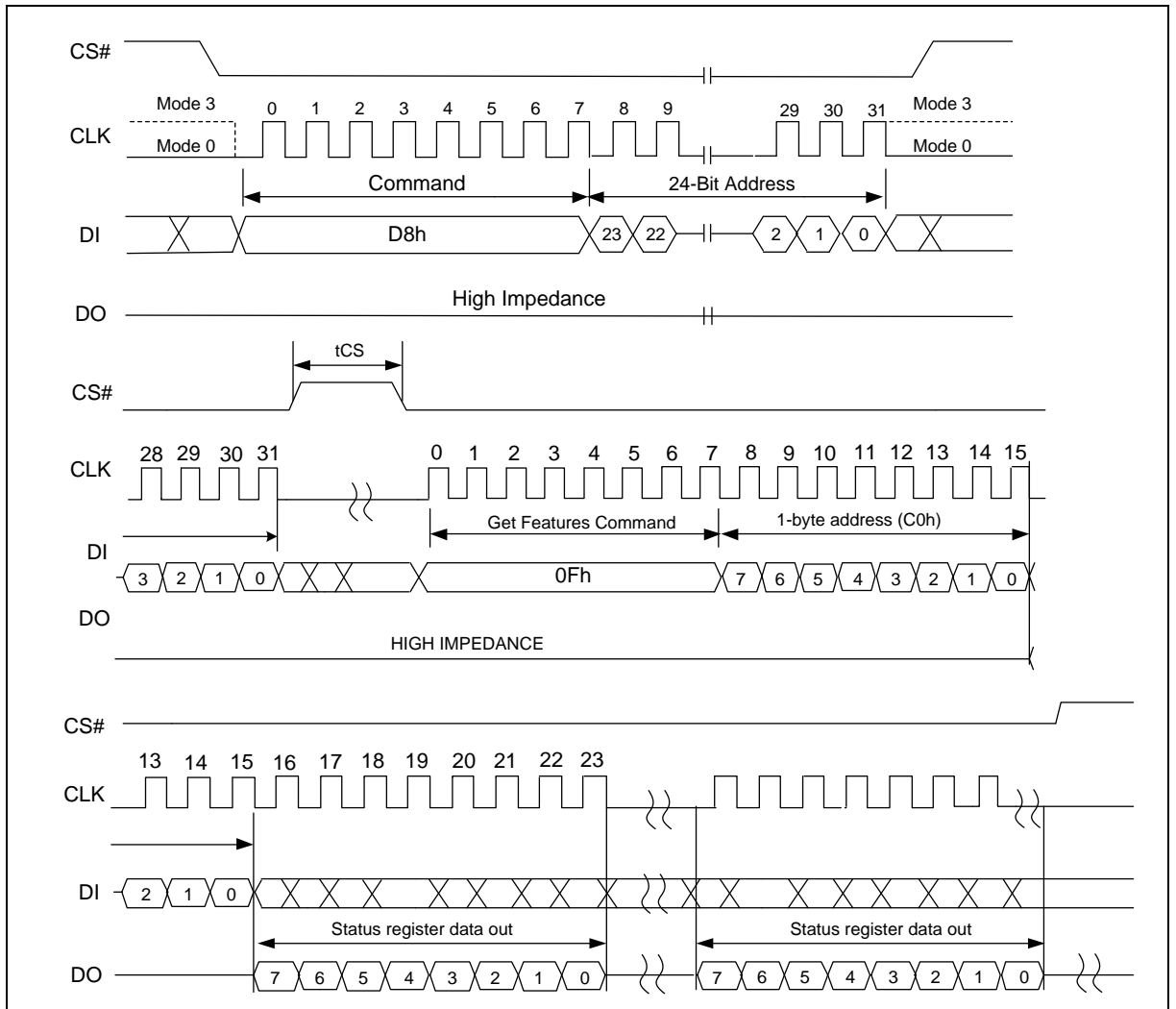
### 9.6.1. BLOCK ERASE (D8h)

The BLOCK ERASE (D8h) command is used to erase at the block level. The blocks are organized as 64 pages per block, 2112 bytes per page (2048 + 64 bytes). Each block is 132 Kbytes. The BLOCK ERASE command (D8h) operates on one block at a time. The command sequence for the BLOCK ERASE operation is as follows:

- 06h (WRITE ENBALE command)
- D8h (BLOCK ERASE command)
- 0Fh (GET FEATURE command to read the status register)

Prior to performing the BLOCK ERASE operation, a WRITE ENABLE (06h) command must be issued. As with any command that changes the memory contents, the WRITE ENABLE command must be executed in order to set the WEL bit. If the WRITE ENABLE command is not issued, then the rest of the erase sequence is ignored. A WRITE ENABLE command must be followed by a BLOCK ERASE (D8h) command. This command requires a 24-bit address consisting of 8 dummy bits followed by a 16-bit row address. After the row address is registered, the control logic automatically controls timing and erase-verify operations. The device is busy for  $t_{ERS}$  time during the BLOCK ERASE operation. The GET FEATURE (0Fh) command can be used to monitor the status of the operation (refer to the Status Register section).

Figure 28 BLOCK ERASE (D8h) Timing

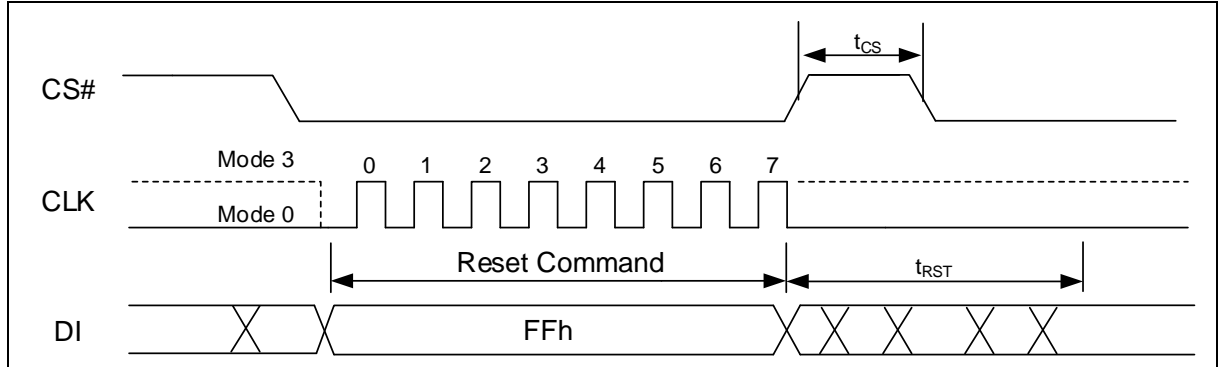


## 9.7. RESET Operation

### 9.7.1. RESET (FFh)

The RESET (FFh) command after POWER ON sequence stops all operations. For example, in case of a program or erase or read operation, the reset command can make the device enter the standby state after  $t_{RST}$ .

Figure 29 RESET (FFh) Timing



## 9.8. Write Protection

The write protection will be determined by the combination of TB, BP[3:0] bits in the Block Lock Register (A0h).

Table 10 Block Lock Register Block Protect Bits

TB	BP3	BP2	BP1	BP0	Protected Row Address	Protected Rows
X	0	0	0	0	None	None; all unlocked
0	0	0	0	1	0FF80h~0FFFFh	Upper 1/512 locked (BLK1022 & 1023)
0	0	0	1	0	0FF00h~0FFFFh	Upper 1/256 locked
0	0	0	1	1	0FE00h~0FFFFh	Upper 1/128 locked
0	0	1	0	0	0FC00h~0FFFFh	Upper 1/64 locked
0	0	1	0	1	0F800h~0FFFFh	Upper 1/32 locked
0	0	1	1	0	0F000h~0FFFFh	Upper 1/16 locked
0	0	1	1	1	0E000h~0FFFFh	Upper 1/8 locked
0	1	0	0	0	0C000h~0FFFFh	Upper 1/4 locked
0	1	0	0	1	08000h~0FFFFh	Upper 1/2 locked
1	0	0	0	1	00000h~0007Fh	Lower 1/512 locked (BLK0 & 1)
1	0	0	1	0	00000h~000FFh	Lower 1/256 locked
1	0	0	1	1	00000h~001FFh	Lower 1/128 locked
1	0	1	0	0	00000h~003FFh	Lower 1/64 locked
1	0	1	0	1	00000h~007FFh	Lower 1/32 locked
1	0	1	1	0	00000h~00FFFh	Lower 1/16 locked
1	0	1	1	1	00000h~01FFFh	Lower 1/8 locked
1	1	0	0	0	00000h~03FFFh	Lower 1/4 locked
1	1	0	0	1	00000h~07FFFh	Lower 1/2 locked
X	1	0	1	X	All	All locked
X	1	1	X	X	All	All locked

NOTE:

1. X = don't care

2. Any Erase or Program command for the protected area will be ignored.

## 10. Unique ID/Parameter/OTP Pages

In addition to the main memory array, the FM25S01A is also equipped with one Unique ID Page, one Parameter Page, and twenty-five OTP Pages.

Page Address	Page Name	Descriptions	Data Length
00h	Unique ID Page	Factory programmed, Read Only	32-ByteX16
01h	Parameter Page	Factory programmed, Read Only	256-ByteX3
02h	OTP Page[0]	Program Only, OTP lockable	2,112-Byte
...	OTP Page[1:23]	Program Only, OTP lockable	2,112-Byte
1Ah	OTP Page[24]	Program Only, OTP lockable	2,112-Byte

To access these additional data pages, the OTP-EN bit in the Status Register-2 must be set to "1" first. Then, Read operations can be performed on the Unique ID and Parameter Pages, Read and Program operations can be performed on the OTP pages if it's not already locked. To return to the main memory array operation, OTP\_EN bit needs to be set to 0.

The device offers a protected, One-Time Programmable NAND Flash memory area. Twenty-five full pages (2112 bytes per page) are available on the device, and the entire range is guaranteed to be good. Customers can use the OTP area any way they want, like programming serial numbers, or other data, for permanent storage. When delivered from factory, feature bit OTP\_PRT is 0.

To access the OTP feature, the user must issue the SET FEATURE command, followed by feature address B0h. When the OTP is ready for access, pages 02h–1Ah can be programmed in sequential order. Every page can program only **ONCE**. The PROGRAM LOAD (02H/32H) and PROGRAM EXECUTE (10H) commands can be used to program the pages. Also, the PAGE READ (13H) command and READ FROM CACHE (03h/0Bh/3Bh/6Bh/BBh/EBh) commands can be used to read the OTP area. The data bits used in feature address B0h to enable OTP access are shown in the table below.

### OTP Access

To access OTP, perform the following command sequence:

- Issue the SET FEATURE command (1Fh) to set OTP\_EN
- Issue the SET FEATURE command (1Fh) to reset BP3~BP0 to all 0 before PAGE PROGRAM.
- Issue the PAGE PROGRAM (if OTP\_EN=1) or PAGE READ command. Every page can program only **ONCE**.

It is important to note that after bits 6 and 7 of the Configuration register are set by the user, the OTP area becomes read-only and no further programming is supported. For OTP states, see the following table.

### OTP Protect

- Issue the SET FEATURE command (1FH) to set OTP\_EN and OTP\_PRT
- Issue the SET FEATURE command (1Fh) to reset BP3~BP0 to all 0.
- 06H (WRITE ENABLE)
- Issue the PROGRAM EXECUTE (10H) command
- After power-on, OTP\_PRT is 0(OTP\_PRT is volatile bit). But OTP area is **still** protected by internal flag.



Table 11 OTP States

OTP_PRT	OTP_EN	State
0	0	Normal Operation
0	1	Access OTP region
1	0	Not applicable
1	1	Lock the OTP area



## 10.1. Parameter Page Data Definitions

The Parameter Page contains 3 identical copies of the 256-Byte Parameter Data. The table below lists all the key data byte locations. All other unspecified byte locations have 00h data as default.

**Table 12 Parameter Page Definition**

Byte Number	Descriptions	Values
0~3	Parameter Page signature	4Fh, 4Eh, 46h, 49h
4~5	Revision number	00h
6~7	Feature supported	00h
8~9	Optional command supported	06h,00h
10~31	Reserved	All 00h
32~43	Device manufacture	46h,55h,44h,41h,4eh,4dh,49h,43h,52h,4fh, 20h, 20h
44~63	Device model	46h,4dh,32h,35h,53h,30h,31h,41h, 20h,20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h
64	Manufacture ID	A1h
65~66	Date code	00h,00h
67~79	Reserved	All 00h
80~83	Number of data bytes per page	00h, 08h, 00h, 00h
84~85	Number of spare bytes per page	40h, 00h
86~91	Reserved	All 00h
92~95	Number of pages per block	40h, 00h, 00h, 00h
96~99	Number of blocks per block unit	00h, 04h, 00h, 00h
100	Number of logic units	01h
101	Number of address bytes	00h
102	Number of bits per cell	01h
103~104	Bad blocks maximum per unit	14h, 00h
105~106	Block endurance	01h,05h
107	Guaranteed valid blocks at beginning of target	01h
108~109	Block endurance for guaranteed valid blocks	00h,00h
110	Number of programs per page	04h
111	Reserved	All 00h
112	Number of ECC bits	00h
113	Number of plane address bits	00h
114	Multi-plane operation attribute	00h
115~127	Reserved	All 00h
128	I/O pin capacitance, maximum	08h
129~132	Reserved	All 00h
133~134	Maximum page program time ( $\mu$ s)	84h,03h
135~136	Maximum block erase time ( $\mu$ s)	10h,27h
137~138	Maximum page read time ( $\mu$ s)	64h,00h
139~163	Reserved	All 00h
164~165	Vendor specified revision number	00h,00h
166~253	Vendor specific	All 00h
254~255	Integrity CRC	Set at test
256~511	Value of bytes 0~255	
512~767	Value of bytes 0~255	
768+	Reserved	

# 11. Error Management

This NAND Flash device is specified to have the minimum number of valid blocks (NVB) of the total available blocks per die shown in the table below. This means the devices may have blocks that are invalid when shipped from the factory. An invalid block is one that contains at least one page that has more bad bits than can be corrected by the minimum required ECC. Additional bad blocks may develop with use. However, the total number of available blocks will not fall below NVB during the endurance life of the product.

Although NAND Flash memory devices may contain bad blocks, they can be used reliably in systems that provide bad-block management and error-correction algorithms. This ensures data integrity.

Internal circuitry isolates each block from other blocks, so the presence of a bad block does not affect the operation of the rest of the NAND Flash array.

NAND Flash devices are shipped from the factory erased. The factory identifies invalid blocks before shipping by attempting to program the bad-block mark into every location in the first and second page of each invalid block. It may not be possible to program every location in an invalid block with the bad-block mark. However, the first spare area location (800h) in each bad block is guaranteed to contain the bad-block mark. This method is compliant with ONFI factory defect mapping requirements. See the following table for the bad-block mark.

System software should initially check the first spare area location (800h) for non-FFh data on the page 0 and page 1 of each block prior to performing any program or erase operations on the NAND Flash device. A bad-block table can then be created, enabling system software to map around these areas. Factory testing is performed under worst-case conditions. Because invalid blocks may be marginal, it may not be possible to recover the bad-block marking if the block is erased.

**Table 13 Error Management Details**

Description	Requirement
Minimum number of valid blocks ( $N_{VB}$ )	1004
Total available blocks per die	1024
First spare area location	Column 2048 of page 0 and page 1
Bad-block mark	Non FFh

## 12. ECC Protection

The device offers data corruption protection by offering optional internal ECC. READs and PROGRAMs with internal ECC can be enabled or disabled by setting feature bit ECC\_E. ECC is enabled after device power up, so the default READ and PROGRAM commands operate with internal ECC in the active state.

To enable/disable ECC, perform the following command sequence:

- Issue the SET FEATURE command (1FH).
- Set the feature bit ECC\_E as you want:
  1. To enable ECC, Set ECC\_E to 1.
  2. To disable ECC, Clear ECC\_E to 0.

During a PROGRAM operation, the device calculates an ECC code on the 2k page in the cache register, before the page is written to the NAND Flash array.

During a READ operation, the page data is read from the array to the cache register, where the ECC code is calculated and compared with the ECC code value read from the array. If error bits are detected, the error is corrected in the cache register. Only corrected data is output on the I/O bus. The ECC status bit indicates whether or not the error correction was successful. The ECC Protection table below shows the ECC protection scheme used throughout a page.

The device will automatically read first page of first block to cache after power on, then host can directly read data from cache for easy boot. Also the data is promise correctly by internal ECC.

With internal ECC, the user must accommodate the following:

- Spare area definitions provided in the ECC Protection table below.
- ECC can protect according main and spare areas. WRITEs to the ECC area are ignored.

**Table 14 ECC Protection and Spare Area**

Min Byte Address	Max Byte Address	ECC Protected	Number Of Bytes	Area	Description
000H	1FFH	Yes	512	Main 0	User data 0
200H	3FFH	Yes	512	Main 1	User data 1
400H	5FFH	Yes	512	Main 2	User data 2
600H	7FFH	Yes	512	Main 3	User data 3
800H	80FH	Yes	16	Spare 0	User meta data 0
810H	81FH	Yes	16	Spare 1	User meta data 1
820H	82FH	Yes	16	Spare 2	User meta data 2
830H	83FH	Yes	16	Spare 3	User meta data 3

NOTE:

1. Spare 800h byte is for bad block marker
2. Spare area 800H to 83FH is all available for user. ECC parity codes are programmed in additional space and not user accessible.

## 13. Electrical Characteristics

### 13.1. Absolute Maximum Ratings

Table 15 Absolute Maximum Ratings

Operating Temperature	-40°C to +85°C
Storage Temperature	-65°C to +150°C
Voltage on I/O Pin with Respect to Ground	-0.5V to 4.0V
V <sub>CC</sub>	-0.5V to 4.0V

**Note:** Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### 13.2. Pin Capacitance

Table 16 Pin Capacitance

Applicable over recommended operating range from: T<sub>A</sub> = 25°C

Symbol	Test Condition	Max	Units	Conditions
C <sub>IN</sub> <sup>(1)</sup>	Input Capacitance	8	pF	V <sub>IN</sub> = 0V
C <sub>OUT</sub> <sup>(1)</sup>	Output Capacitance	8	pF	V <sub>OUT</sub> = 0V

**Note:** 1. characterized and is not 100% tested.

### 13.3. Power-up Timing

Figure 30 Power-On Timing

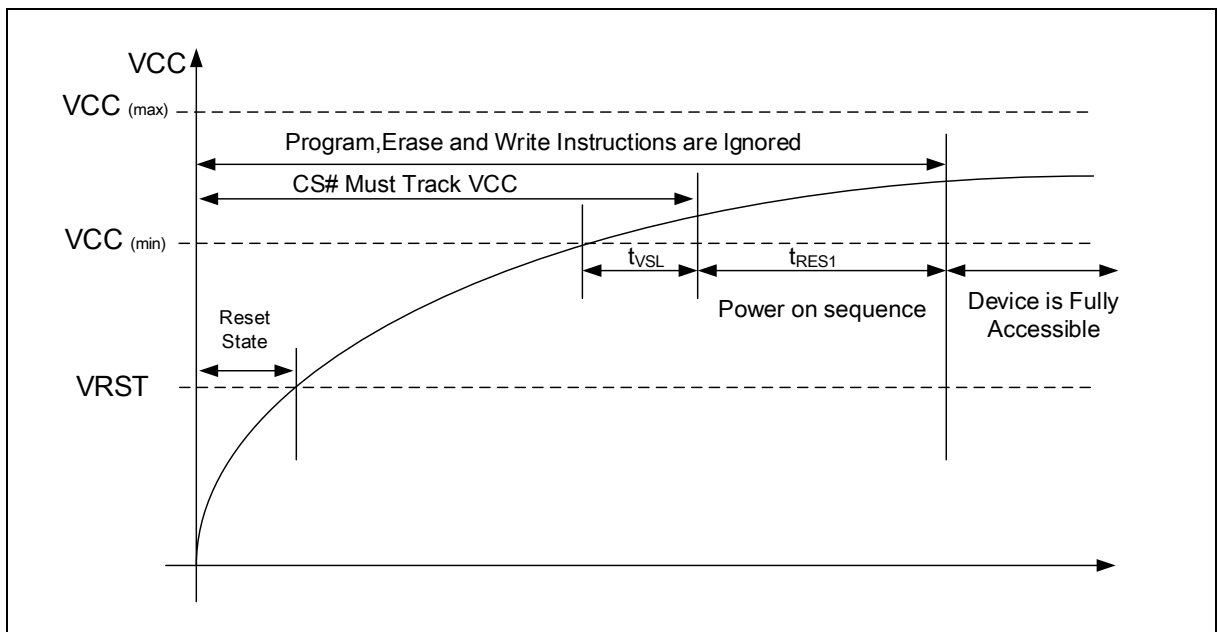


Table 17 Power-On Timing and Write Inhibit Threshold



PARAMETER	SYMBOL	SPEC		UNIT
		MIN	MAX	
VCC (min) to CS# Low	$t_{VSL}$	1		ms
Power on sequence	$t_{RES}$	1		ms
Write Inhibit Voltage	$V_{WI}$		2.5	V
Chip Reset Voltage	$V_{RST}$		2.3	V

## 13.4. DC Electrical Characteristics

Table 18 DC Characteristics

Applicable over recommended operating range from:  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $V_{CC} = 2.7\text{V}$  to  $3.6\text{V}$  (unless otherwise noted).

SYMBOL	PARAMETER	CONDITIONS	SPEC			UNIT
			MIN	TYP	MAX	
$V_{CC}$	Power supply		2.7		3.6	V
$I_{LI}$	Input Leakage Current				$\pm 10$	$\mu\text{A}$
$I_{LO}$	Output Leakage Current				$\pm 10$	$\mu\text{A}$
$I_{SB1}$	Standby Current	$V_{CC} = V_{CCmax}$ , CS# = VCC, $V_{IN} = VSS$ or VCC		10	50	$\mu\text{A}$
$I_{CC1}$	Operating Current	$F_{CLK} = 104\text{MHz}$ , CS# = VIL, $I_{out} = 0\text{mA}$ , Page Read		16	20	mA
$I_{CC2}$		Program		16	20	mA
$I_{CC3}$		Erase		16	20	mA
$V_{IL}^{(1)}$	Input Low Voltage		-0.3		$0.2V_{CC}$	V
$V_{IH}^{(1)}$	Input High Voltage		$0.7V_{CC}$		$V_{CC} + 0.3$	V
$V_{OL}$	Output Low Voltage	$I_{OL} = 1\text{mA}$			$0.15V_{CC}$	V
$V_{OH}$	Output High Voltage	$I_{OH} = -20\mu\text{A}$	$0.7V_{CC}$			V

**Notes:**

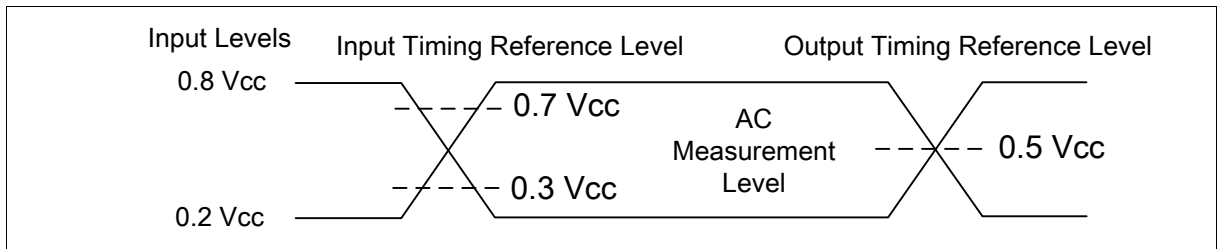
- $V_{IL}$  min and  $V_{IH}$  max are reference only and are not tested.

## 13.5. AC Measurement Conditions

Table 19 AC Measurement Conditions

SYMBOL	PARAMETER	SPEC		UNIT
		MIN	MAX	
CL	Load Capacitance		15	pF
TR, TF	Input Rise and Fall Times		5	ns
VIN	Input Pulse Voltages	0.2 V <sub>CC</sub> to 0.8 V <sub>CC</sub>		V
IN	Input Timing Reference Voltages	0.3 V <sub>CC</sub> to 0.7 V <sub>CC</sub>		V
OUT	Output Timing Reference Voltages	0.5V <sub>CC</sub>		V

Figure 31 AC Measurement I/O Waveform



## 13.6. AC Electrical Characteristics

Table 20 AC Characteristics

Applicable over recommended operating range from: T<sub>A</sub> = -40°C to 85°C, V<sub>CC</sub> = 2.7V to 3.6V, (unless otherwise noted).

SYMBOL	PARAMETER	SPEC			UNIT
		MIN	TYP	MAX	
F <sub>C</sub>	Serial Clock Frequency for all other instructions			104	MHz
F <sub>R</sub>	Serial Clock Frequency for BB,EB command			40	MHz
t <sub>CH1</sub> <sup>(1)</sup>	Serial Clock High Time	4.5			ns
t <sub>CL1</sub> <sup>(1)</sup>	Serial Clock Low Time	4.5			ns
t <sub>CLCH</sub> <sup>(2)</sup>	Serial Clock Rise Time (Slew Rate)	0.1			V/ns
t <sub>CHCL</sub> <sup>(2)</sup>	Serial Clock Fall Time (Slew Rate)	0.1			V/ns
t <sub>SLCH</sub>	CS# Active Setup Time	4.5			ns
t <sub>CHSH</sub>	CS# Active Hold Time	4.5			ns
t <sub>SHCH</sub>	CS# Not Active Setup Time	4.5			ns
t <sub>CHSL</sub>	CS# Not Active Hold Time	4.5			ns
t <sub>SHSL</sub> /t <sub>CS</sub>	CS# High Time	80			ns
t <sub>SHQZ</sub> <sup>(2)</sup>	Output Disable Time			20	ns
t <sub>CLQX</sub>	Output Hold Time	1.5			ns
t <sub>DVCH</sub>	Data In Setup Time	2			ns
t <sub>CHDX</sub>	Data In Hold Time	3			ns
t <sub>HLCH</sub>	HOLD# Low Setup Time ( relative to CLK )	4.5			ns
t <sub>HHCH</sub>	HOLD# High Setup Time ( relative to CLK )	4.5			ns
t <sub>CHHH</sub>	HOLD# Low Hold Time ( relative to CLK )	4.5			ns
t <sub>CHHL</sub>	HOLD# High Hold Time ( relative to CLK )	4.5			ns
t <sub>HLQZ</sub> <sup>(2)</sup>	HOLD# Low to High-Z Output			7	ns

SYMBOL	PARAMETER	SPEC			UNIT
		MIN	TYP	MAX	
$t_{HHQX}^{(2)}$	HOLD# High to Low-Z Output			7	ns
$t_{CLQV}$	Output Valid from CLK			8	ns
$t_{WHSL}$	WP# Setup Time before CS# Low	20			ns
$t_{SHWL}$	WP# Hold Time after CS# High	100			ns
$t_{RST}$	Resetting time during Idle/Read/Program/Erase			5/5/10 /500	$\mu$ s

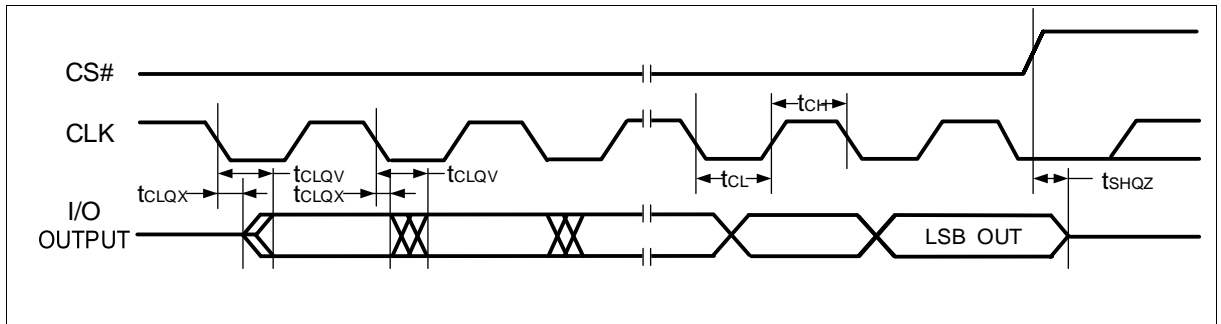
**Notes:**

1.  $T_{CH1} + T_{CL1} \geq 1 / F_C$  ;
2. Characterized and not 100% tested.

**Table 21 Performance Timing**

SYMBOL	PARAMETER	SPEC			UNIT
		MIN	TYP	MAX	
$t_{RD}$	Page Read From Array (with ECC)			100	$\mu$ s
	Page Read From Array (without ECC)			25	
$t_{PROG}$	Page Program		400	900	$\mu$ s
$t_{POTP}$	OTP Page Program		800	2000	$\mu$ s
$t_{ERS}$	Block Erase		4	10	ms

**Figure 32 Serial Output Timing**



**Figure 33 Serial Input Timing**

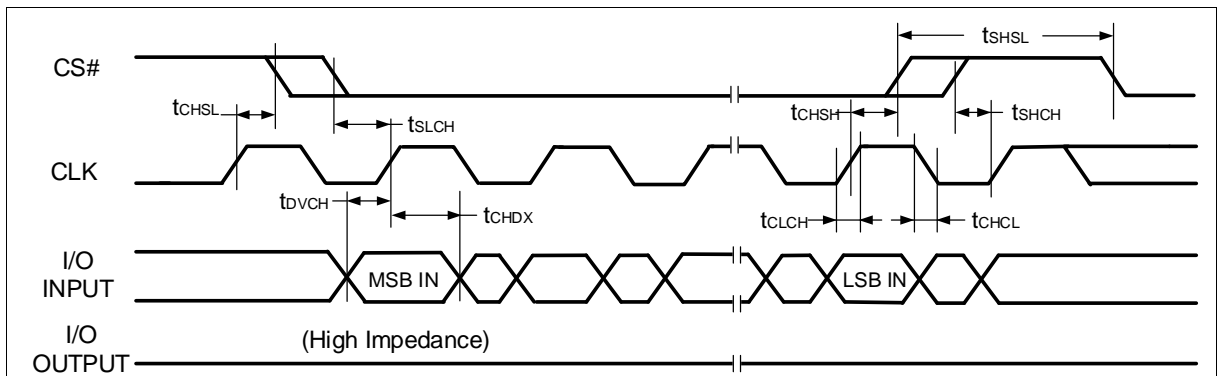


Figure 34 Hold Timing

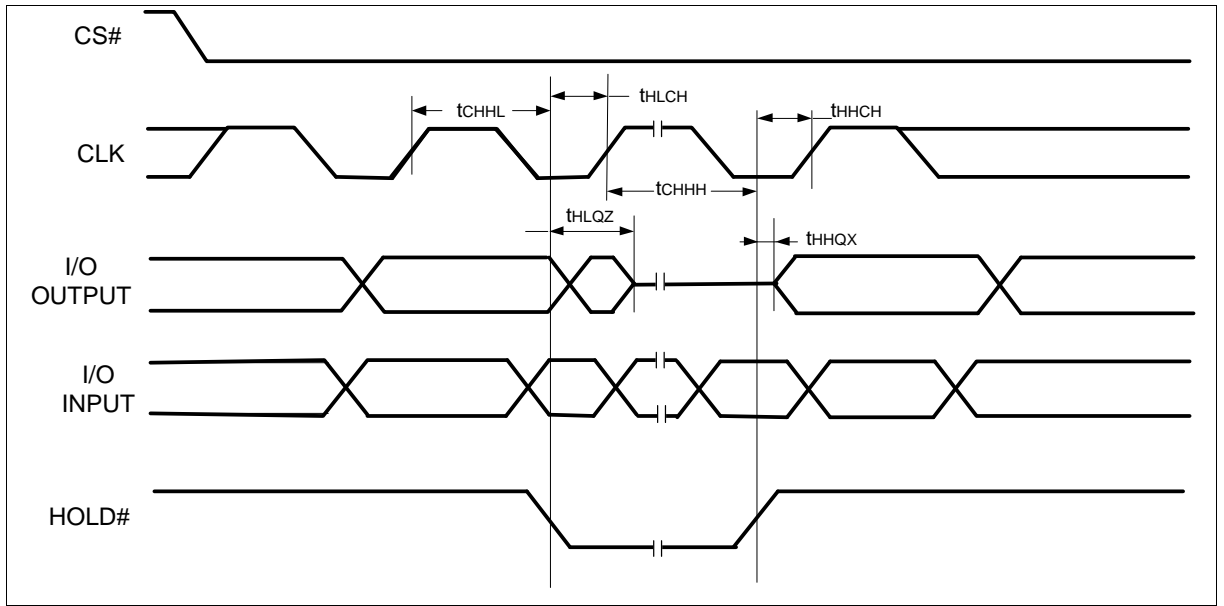
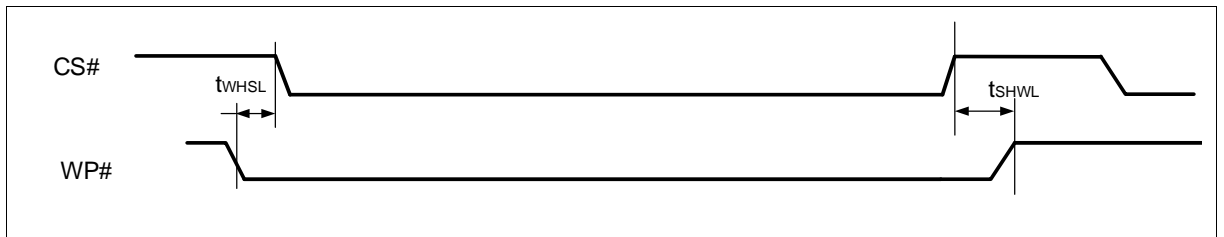


Figure 35 WP Timing







## 14. Ordering Information

	FM	25S	01A	-XXX	-C	-H
<b>Company Prefix</b>						
FM = Fudan Microelectronics Group Co.,Ltd						
<b>Product Family</b>						
25S = 3.3V SPI NAND Flash						
<b>Product Density</b>						
01A = 1G-bit (Page Size 2112-Byte)						
<b>Package Type</b>						
DND = WSON8 8x6mm (TDFN8 8x6mm)						
<b>Product Carrier</b>						
A = Tray						
<b>HSF ID Code</b>						
G = RoHS Compliant, Halogen-free, Antimony-free						

# 15. Part Marking Scheme

## WSON8 8x6mm (TDFN8 8x6mm)



FM25S01A

Product Density

YYWWALH

HSF ID Code

G = RoHS Compliant, Halogen-free, Antimony-free

Package Lot Number (just with 0~9, A~Z)

Assembly's Code

Work week during which the product was molded (eg..week 12)

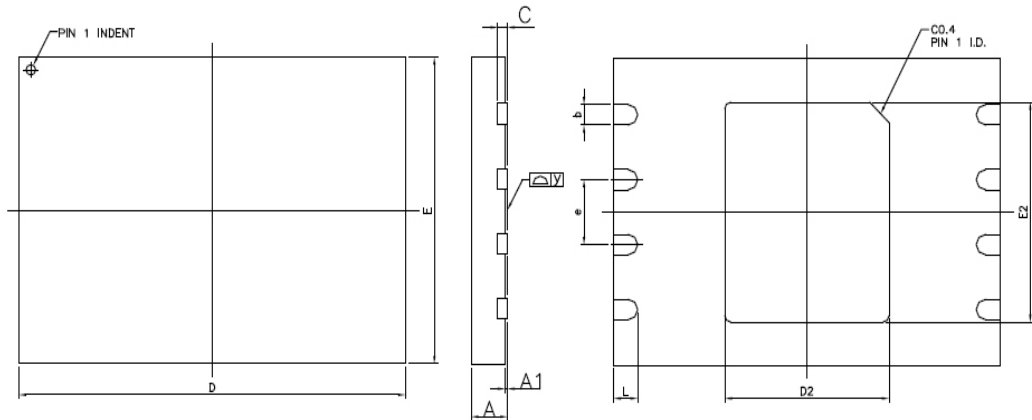
The last two digits of the year in which the product was sealed/molded

XXXXXXXXX

Wafer Lot Number (the length is not fixed)

## 16. Packaging Information

### WSON8 8x6mm (TDFN8 8x6mm)



Symbol	MIN	MAX
e	1.270 BSC	
D	7.900	8.100
E	5.900	6.100
L	0.450	0.550
A	0.700	0.800
A1	0.000	0.050
C	0.180	0.250
b	0.350	0.450
D2	3.300	3.500
E2	4.200	4.400

**Note:**

1. Dimensions are in Millimeters.



## 17. Revision History

Version	Publication date	Pages	Paragraph or Illustration	Revise Description
preliminary	Aug. 2018	45		Initial Document Release



# Sales and Service

## Shanghai Fudan Microelectronics Group Co., Ltd.

Address: Bldg No. 4, 127 Guotai Rd,  
Shanghai City China.

Postcode: 200433

Tel: (86-021) 6565 5050

Fax: (86-021) 6565 9115

## Shanghai Fudan Microelectronics (HK) Co., Ltd.

Address: Unit 506, 5/F., East Ocean Centre, 98 Granville Road, Tsimshatsui  
East, Kowloon, Hong Kong

Tel: (852) 2116 3288 2116 3338

Fax: (852) 2116 0882

## Beijing Office

Address: Room 423, Bldg B, Gehua Building,  
1 QingLong Hutong, Dongzhimen Alley north Street,  
Dongcheng District, Beijing City, China.

Postcode: 100007

Tel: (86-010) 8418 6608

Fax: (86-010) 8418 6211

## Shenzhen Office

Address: Room.1301, Century Bldg, No. 4002, Shengtingyuan Hotel, Huaqiang Rd  
(North),  
Shenzhen City, China.

Postcode: 518028

Tel: (86-0755) 8335 0911 8335 1011 8335 2011 8335 0611

Fax: (86-0755) 8335 9011

## Shanghai Fudan Microelectronics (HK) Ltd Taiwan Representative Office

Address: Unit 1225, 12F., No 252, Sec.1 Neihu Rd., Neihu Dist., Taipei City  
114, Taiwan

Tel : (886-2) 7721 1889 (886-2) 7721 1890

Fax: (886-2) 7722 3888

## Shanghai Fudan Microelectronics (HK) Ltd Singapore Branch Office

Address: 47 Kallang Pudding Road, #08-06  
The Crescent @ Kallang, Singapore 349318

Tel: +65 64430860

Fax: +65 64431215

Email: ktan@fmsh.com

## Fudan Microelectronics (USA) Inc.

Address: 97 E Brokaw Road, Suite 320, San Jose, CA 95112

Tel: (+1)408-335-6936

Contact name: Xinyue Huang

Email: fmus@fmsh.com

Web Site: <http://www.fmsh.com/>